

PHYS-E0525 Microscopy of Nanomaterials P (5 cr)

Prof. Janne Ruokolainen (nanotalo 102)

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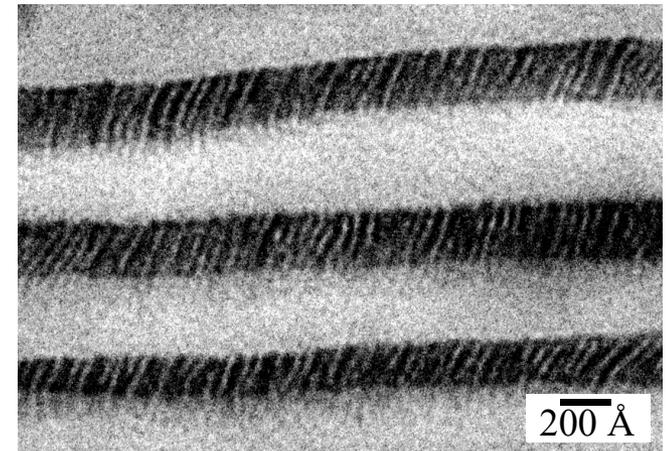
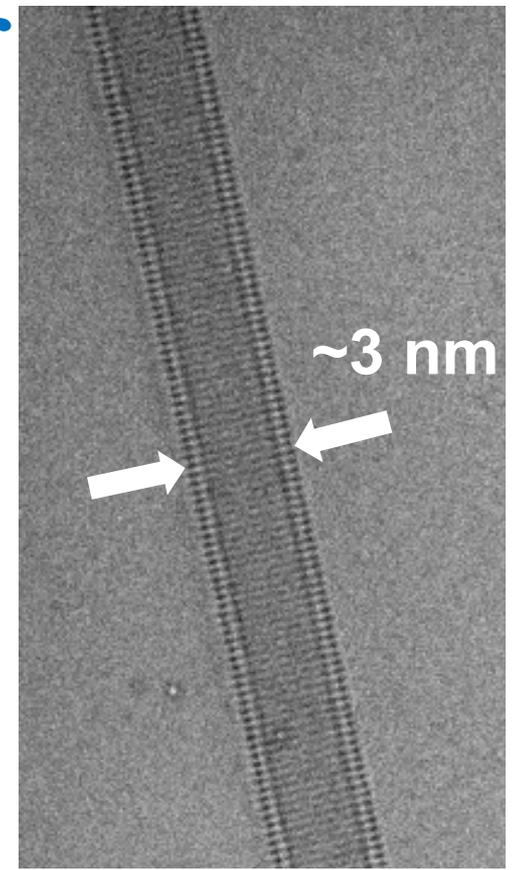
First lecture 17.1. 2023

Tuesday 12.15 – 14

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Course overview:

The course gives basic knowledge of the microscopy of materials nanoscale structures - including soft and hard materials. Lectures will concentrate on **transmission electron microscopy (TEM, STEM): high resolution imaging, electron diffraction and analytical microscopy by using elemental analyses (EDX, EELS), cryo-electron microscopy and 3D electron tomography**. Additionally, **scanning electron microscopy (SEM and FIB), atomic force microscopy (AFM)** and **methods to prepare samples** are lectured..



Lectures:

Prof. Janne Ruokolainen, Dr. Hua Jiang, Dr. Jani Seitsonen, Dr. Ramzy Abdelaziz, Prof. Peter Liljeroth, Dr. Lide Yao

Tentative Schedule

- 17. 1. Introduction & Nanomicroscopy center (JR)
- 24. 1. TEM Basics (JR)
- 31. 1. Advanced TEM 1 (Hua)
- 7. 2. Advanced TEM 2 (Hua)
- 14. 2. Advanced TEM 3 (Hua)
- 21. 2. *no lecture (exam period at Aalto)*
- 28. 2. Cryo-TEM and Soft matter Sample preparation (JR)
- 7. 3. SEM (Ramzy)
- 14. 3. 3D-TEM-Tomography (Jani)
- 21. 3. FIB and Sample preparation (Lide)
- 28. 3. STM/AFM (Peter)

Summary:

Intro, Basic TEM, Cryo TEM ~ 3 lectures
Advanced TEM 2-3 lectures
(High resolution TEM and STEM,
diffraction, spectroscopy EDX, EELS)
STM/AFM
FIB/sample preparation
SEM
Tomography

Additional Literature: (optional)

Book 1: *Transmission electron microscopy Basics I (David William and Barry Carter) 2nd edition*

Book 2: *G.H. Michler "Electron microscopy of polymers" (TEM, SEM, AFM..)*

Book 3: *A practical Guide to Transmission Electron Microscopy (Zhiping Luo)*

Additional Literature if you are interested to study more in this topic..

Book 1: Transmission electron microscopy Basics Part I (David William and Barry Carter) 2nd edition

This book has *more theory*, and it also has lots of technical information about microscope (vacuum systems, electron sources, sample holders etc..) and it also has 3 other books for Advanced TEM (Part 2: Diffraction , Part 3: high resolution imaging and Part 4: Spectroscopy)

Book 2: G.H. Michler "Electron microscopy of polymers" (TEM, SEM, AFM..)

A bit easier book to study – more practical and has also SEM and AFM parts (First 250 pages are useful – rest are specific polymer applications..)

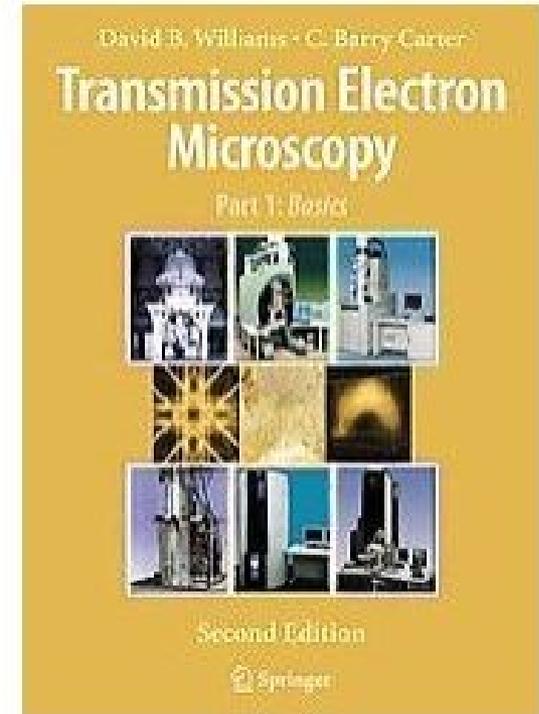
Book 3: A practical Guide to Transmission Electron Microscopy (Zhiping Luo)

This book is **most practical** especially **those who want to learn how to operate microscopes** Chapter **1-3** and (partly chapter 5?) and chapters **7-9**. (chapters 4, 5, and 6 are diffraction and perhaps more advanced level than this course..)

Book 1: Part 1: Basics

Transmission Electron Microscopy A Textbook for Materials Science David B. Williams, C. Barry Carter

PART 1 BASICS	1
1 The Transmission Electron Microscope	3
Chapter Preview	3
1.1 What Materials Should We Study in the TEM?	3
1.2 Why Use Electrons?	4
1.2.A An Extremely Brief History	4
1.2.B Microscopy and the Concept of Resolution	5
1.2.C Interaction of Electrons with Matter	7
1.2.D Depth of Field and Depth of focus	8
1.2.E Diffraction	8
1.3 Limitations of the TEM	9
1.3.A Sampling	9
1.3.B Interpreting Transmission Images	9
1.3.C Electron Beam Damage and Safety	10
1.3.D Specimen Preparation	11
1.4 Different Kinds of TEMs	11
1.5 Some Fundamental Properties of Electrons	11
1.6 Microscopy on the Internet/World Wide Web	15
1.6.A Microscopy and Analysis-Related Web Sites	15
1.6.B Microscopy and Analysis Software	15
Chapter Summary	17



2	Scattering and Diffraction	23
	Chapter Preview	23
2.1	Why Are We Interested in Electron Scattering?	23
2.2	Terminology of Scattering and Diffraction	25
2.3	The Angle of Scattering	26
2.4	The Interaction Cross Section and Its Differential	27
	2.4.A Scattering from an Isolated Atom	27
	2.4.B Scattering from the Specimen	28
	2.4.C Some Numbers	28
2.5	The Mean Free Path	28
2.6	How We Use Scattering in the TEM	29
2.7	Comparison to X-ray Diffraction	30
2.8	Fraunhofer and Fresnel Diffraction	30
2.9	Diffraction of Light from Slits and Holes	31
2.10	Constructive Interference	33
2.11	A Word About Angles	34
2.12	Electron-Diffraction Patterns	34
	Chapter Summary	36
3	Elastic Scattering	39
	Chapter Preview	39
3.1	Particles and Waves	39
3.2	Mechanisms of Elastic Scattering	40
3.3	Elastic Scattering from Isolated Atoms	41
3.4	The Rutherford Cross Section	41
3.5	Modifications to the Rutherford Cross Section	42
3.6	Coherency of the Rutherford-Scattered Electrons	43
3.7	The Atomic-Scattering Factor	44
3.8	The Origin of $f(\theta)$	45
3.9	The Structure Factor $F(\theta)$	46
3.10	Simple Diffraction Concepts	47
	3.10.A Interference of Electron Waves; Creation of the Direct and Diffracted Beams	47
	3.10.B Diffraction Equations	48
	Chapter Summary	49

4	Inelastic Scattering and Beam Damage	53
	Chapter Preview	53
4.1	Which Inelastic Processes Occur in the TEM?	53
4.2	X-ray Emission	55
	4.2.A Characteristic X-rays	55
	4.2.B Bremsstrahlung X-rays	60
4.3	Secondary-Electron Emission	60
	4.3.A Secondary Electrons	60
	4.3.B Auger Electrons	61
4.4	Electron-Hole Pairs and Cathodoluminescence (CL)	62
4.5	Plasmons and Phonons	63
4.6	Beam Damage	64
	4.6.A Electron Dose	65
	4.6.B Specimen Heating	65
	4.6.C Beam Damage in Polymers	66
	4.6.D Beam Damage in Covalent and Ionic Crystals	66
	4.6.E Beam Damage in Metals	66
	4.6.F Sputtering	68
	Chapter Summary	68
5	Electron Sources	73
	Chapter Preview	73
5.1	The Physics of Different Electron Sources	73
	5.1.A Thermionic Emission	74
	5.1.B Field Emission	74
5.2	The Characteristics of the Electron Beam	75
	5.2.A Brightness	75
	5.2.B Temporal Coherency and Energy Spread	76
	5.2.C Spatial Coherency and Source Size	77
	5.2.D Stability	77
5.3	Electron Guns	77
	5.3.A Thermionic Guns	77
	5.3.B Field-Emission Guns (FEGs)	80
5.4	Comparison of Guns	81
5.5	Measuring Your Gun Characteristics	82
	5.5.A Beam Current	82
	5.5.B Convergence Angle	83
	5.5.C Calculating the Beam Diameter	83
	5.5.D Measuring the Beam Diameter	85
	5.5.E Energy Spread	85
	5.5.F Spatial Coherency	86
5.6	What kV should You Use?	86
	Chapter Summary	87

6	Lenses, Apertures, and Resolution	91
	Chapter Preview	91
6.1	Why Learn About Lenses?	91
6.2	Light Optics and Electron Optics	92
	6.2.A How to Draw a Ray Diagram	92
	6.2.B The Principal Optical Elements	94
	6.2.C The Lens Equation	94
	6.2.D Magnification, Demagnification, and Focus	95
6.3	Electron Lenses	96
	6.3.A Polepieces and Coils	96
	6.3.B Different Kinds of Lenses	97
	6.3.C Electron Ray Paths Through Magnetic Fields	99
	6.3.D Image Rotation and the Eucentric Plane	100
	6.3.E Deflecting the Beam	101
6.4	Apertures and Diaphragms	101
6.5	Real Lenses and their Problems	102
	6.5.A Spherical Aberration	103
	6.5.B Chromatic Aberration	104
	6.5.C Astigmatism	106
6.6	The Resolution of the Electron Lens (and Ultimately of the TEM)	106
	6.6.A Theoretical Resolution (Diffraction-Limited Resolution)	107
	6.6.B The Practical Resolution Due to Spherical Aberration	108
	6.6.C Specimen-Limited Resolution Due to Chromatic Aberration	109
	6.6.D Confusion in the Definitions of Resolution	109
6.7	Depth of Focus and Depth of Field	110
	Chapter Summary	111

7	How to ‘See’ Electrons	115
	Chapter Preview	115
	7.1 Electron Detection and Display	115
	7.2 Viewing Screens	116
	7.3 Electron Detectors	117
	7.3.A Semiconductor Detectors	117
	7.3.B Scintillator-Photomultiplier Detectors/TV Cameras	118
	7.3.C Charge-Coupled Device (CCD) Detectors	120
	7.3.D Faraday Cup	121
	7.4 Which Detector Do We Use for which Signal?	122
	7.5 Image Recording	122
	7.5.A Photographic Emulsions	122
	7.5.B Other Image-Recording Methods	124
	7.6 Comparison of Scanning Images and Static Images	124
	Chapter Summary	125
8	Pumps and Holders	127
	Chapter Preview	127
	8.1 The Vacuum	127
	8.2 Roughing Pumps	128
	8.3 High/Ultra High Vacuum Pumps	129
	8.3.A Diffusion Pumps	129
	8.3.B Turbomolecular Pumps	129
	8.3.C Ion Pumps	130
	8.3.D Cryogenic (Adsorption) Pumps	130
	8.4 The Whole System	130
	8.5 Leak Detection	131
	8.6 Contamination: Hydrocarbons and Water Vapor	132
	8.7 Specimen Holders and Stages	132
	8.8 Side-Entry Holders	133
	8.9 Top-entry Holders	134
	8.10 Tilt and Rotate Holders	134
	8.11 In-Situ Holders	135
	8.12 Plasma Cleaners	138
	Chapter Summary	138

9	The Instrument	141
	Chapter Preview	141
9.1	The Illumination System	142
	9.1.A TEM Operation Using a Parallel Beam	142
	9.1.B Convergent-Beam (S)TEM Mode	143
	9.1.C The Condenser-Objective Lens	145
	9.1.D Translating and Tilting the Beam	147
	9.1.E Alignment of the C2 Aperture	147
	9.1.F Condenser-Lens Defects	148
	9.1.G Calibration	149
9.2	The Objective Lens and Stage	150
9.3	Forming DPs and Images: The TEM Imaging System	152
	9.3.A Selected-Area Diffraction	152
	9.3.B Bright-Field and Dark-Field Imaging	155
	9.3.C Centered Dark-Field Operation	155
	9.3.D Hollow-Cone Diffraction and Dark-Field Imaging	157
9.4	Forming DPs and Images: The STEM Imaging System	158
	9.4.A Bright-Field STEM Images	159
	9.4.B Dark-Field STEM Images	161
	9.4.C Annular Dark-Field Images	161
	9.4.D Magnification in STEM	161
9.5	Alignment and Stigmatism	161
	9.5.A Lens Rotation Centers	161
	9.5.B Correction of Astigmatism in the Imaging Lenses	162
9.6	Calibrating the Imaging System	164
	9.6.A Magnification Calibration	164
	9.6.B Camera-Length Calibration	165
	9.6.C Rotation of the Image Relative to the DP	167
	9.6.D Spatial Relationship Between Images and DPs	168
9.7	Other Calibrations	168
	Chapter Summary	169

10 Specimen Preparation	173
Chapter Preview	173
10.1 Safety	173
10.2 Self-Supporting Disk or Use a Grid?	174
10.3 Preparing a Self-Supporting Disk for Final Thinning	175
10.3.A Forming a Thin Slice from the Bulk Sample	176
10.3.B Cutting the Disk	176
10.3.C Prethinning the Disk	177
10.4 Final Thinning of the Disks	178
10.4.A Electropolishing	178
10.4.B Ion Milling	178
10.5 Cross-Section Specimens	182
10.6 Specimens on Grids/Washers	183
10.6.A Electropolishing—The Window Method for Metals and Alloys	183
10.6.B Ultramicrotomy	183
10.6.C Grinding and Crushing	184
10.6.D Replication and Extraction	184
10.6.E Cleaving and the SACT	186
10.6.F The 90° Wedge	186
10.6.G Lithography	187
10.6.H Preferential Chemical Etching	187
10.7 FIB	188
10.8 Storing Specimens	189
10.9 Some Rules	189
Chapter Summary	191

Book 2:



SPRINGER LABORATORY

G. H. Michler

Electron Microscopy of Polymers

 Springer

Part I Techniques of Electron Microscopy

1	OVERVIEW OF TECHNIQUES	7
	References	14
2	TRANSMISSION ELECTRON MICROSCOPY: FUNDAMENTALS OF METHODS AND INSTRUMENTATION	15
2.1	A Brief History	15
2.2	Fundamentals of Electron Optics and Instrumentation	17
2.2.1	Some Fundamental Properties of Electrons	17
2.2.2	Electron Lenses	19
2.2.3	Electron-Optical Aberrations and Resolution	22
2.2.4	Vacuum System	26
2.3	The Instrument	27
2.3.1	Electron Gun	30
2.3.2	Illumination System	33
2.3.3	Objective Lens and Specimen Stage	35
2.3.4	Image-Forming System	36
2.3.5	Viewing Chamber and Image Acquisition	37
2.3.6	Alignment and Operation of Transmission Electron Microscopes	39
2.4	Fundamentals of Image Formation	40
2.4.1	Scattering Mechanism and Contrast Formation	41
2.4.2	Electron Diffraction and Diffraction Contrast	44
2.4.3	Fundamentals of the Imaging Process	46
	References	50

3	TRANSMISSION ELECTRON MICROSCOPY: CONVENTIONAL AND SPECIAL INVESTIGATIONS OF POLYMERS	53
3.1	Conventional Investigations Utilising Mass-Thickness Contrast	53
3.2	Electron Diffraction	55
3.2.1	Selected Area Diffraction	55
3.2.2	Structure Analysis	55
3.3	High-Resolution Transmission Electron Microscopy	57
3.3.1	Introduction	57
3.3.2	Evaluation and Reduction of Radiation Damage	57
3.3.3	Application of HRTEM	58
3.4	Phase Contrast Transmission Electron Microscopy	60
3.4.1	Phase Contrast at Large Defocus Values	60
3.4.2	Phase Contrast by Means of Phase Plates	60
3.5	Electron Holography	62
3.5.1	Introduction	62
3.5.2	Image Plane Off-Axis Holography	62
3.5.3	Examples	64
3.6	Low-Voltage Transmission Electron Microscopy	64
3.6.1	Introduction	64
3.6.2	A Dedicated Low-Voltage TEM and its Application	64
3.7	High-Voltage Transmission Electron Microscopy	65
3.7.1	Introduction	65
3.7.2	Advantages and Applications of HVTEM	65
3.8	Scanning Transmission Electron Microscopy	66
3.8.1	Introduction	66
3.8.2	Similarities and Differences between STEM and TEM	67
3.8.3	Application of Bright-Field and Dark-Field Modes	68
3.9	Analytical Transmission Electron Microscopy	70
3.9.1	Introduction	70
3.9.2	EELS Investigations	72
3.9.3	Electron Spectroscopic Imaging	75
3.10	Electron Tomography	78
3.10.1	Introduction	78
3.10.2	Data Acquisition, Image Alignment and Reconstruction	79
3.10.3	Resolution of Reconstructed Data	80
3.10.4	Application of Electron Tomography	81
	References	81

4	SCANNING ELECTRON MICROSCOPY (SEM)	87
4.1	A Brief History of SEM	87
4.2	Fundamentals of Electron Optics and Signal Generation	88
4.2.1	Principle of SEM	88
4.2.2	The Lateral Resolution Power of SEM	89
4.2.3	Comparison of Various Cathode Types	92
4.2.4	Depth of Focus	92
4.2.5	Interaction of Primary Electrons with Sample	92
4.3	The Instrumentation of SEM	95
4.3.1	The Column	95
4.3.2	Specimen Chamber and Goniometer	97
4.3.3	Detectors	98
4.3.4	Signal Display and Magnification	99
4.4	Contrast Formation and Charging Effects	100
4.4.1	Secondary Electron Contrast	100
4.4.2	Contrast of Backscattered Electrons (Solid State Detector) .	103
4.4.3	Charging Effect	103
4.5	X-Ray Microanalysis	105
4.5.1	Physical Fundamentals of the Generation of X-Rays	105
4.5.2	X-Ray Microanalysis Techniques	107
4.5.3	Detector for EDX Analysis	108
4.5.4	Quantitative EDX Analysis	111
4.5.5	X-Ray Mapping	112
4.5.6	Wavelength Dispersive X-Ray Microanalysis (WDX)	112
4.6	Environmental Scanning Electron Microscope (ESEM™)	116
4.6.1	Low-Vacuum SEM and ESEM™	116
4.6.2	Avoiding Charging	116
4.6.3	The Wet Mode	117
4.6.4	The Gaseous Secondary Electron Detector (GSED)	119
	References	120

5	ATOMIC FORCE MICROSCOPY (AFM)	121
5.1	Introduction	121
5.2	Methodical and Instrumental Fundamentals	124
5.3	Modes of Operation.....	127
5.3.1	Contact Mode	127
5.3.2	Force Modulation Mode	130
5.3.3	Dynamic Operational Modes	131
5.3.4	Tapping Mode	132
5.4	Typical and Special AFM Applications	137
	References	142
6	IN SITU MICROSCOPY	145
6.1	Overview	145
6.2	Micromechanical In Situ Tests	147
6.2.1	Technical Equipment	147
6.2.2	In Situ Microscopy in (E)SEM	148
6.2.3	In Situ Microscopy in (HV)TEM	150
6.3	In Situ Microscopy in AFM	154
	References	158
7	IMAGE PROCESSING AND IMAGE ANALYSIS	161
7.1	Overview	161
7.2	Image Processing	162
7.3	Image Analysis	163
7.4	Fourier Transformation	165
7.5	Stereoscopic Imaging	167
	References	171

8	PROBLEMS ASSOCIATED WITH THE ELECTRON MICROSCOPY OF POLYMERS	175
8.1	Overview	175
8.2	Irradiation Sensitivity of Polymers	176
8.3	Low Contrast of Polymers	177
8.4	Methods of Investigating the Morphologies of Polymers	178
8.4.1	Powders, Particles, Fibres	178
8.4.2	Bulk Polymers	178
8.5	Methods for Studying Micromechanical Processes	180
	References	183
9	PREPARATION OF SURFACES	185
9.1	Overview	185
9.2	Surfaces in Their Natural Form	185
9.3	Smooth and Etched Surfaces	186
9.3.1	Chemical Etching	187
9.3.2	Physical Etching	191
9.4	Fracture Surfaces	192
9.5	Investigation of Surfaces	195
	References	196
10	PREPARATION OF THIN SECTIONS: (CRYO)ULTRAMICROTOMY AND (CRYO)MICROTOMY	199
10.1	Overview	199
10.2	Instrumentation	200
10.2.1	Microtomes	200
10.2.2	Ultramicrotomes	200
10.2.3	Cryomicrotomes and Cryoultramicrotomes	200
10.2.4	Knives	200
10.2.5	Modern Trends	202
10.3	Working with a Microtome and an Ultramicrotome	203
10.4	Specimen Preparation	204
10.4.1	Embedding	204
10.4.2	Specimen Trimming	205
10.4.3	Fixation and Staining	205
10.5	Ultrathin Sectioning	206
10.5.1	Sectioning Parameters	206
10.5.2	Wet and Dry Sectioning Techniques	206
10.5.3	Room Temperature Ultramicrotomy	208
10.5.4	Cryoultramicrotomy	208
10.5.5	Collecting Sections on Grids	209
10.6	Problems, Errors and Solutions	212
10.6.1	Overview	212
10.6.2	Typical Errors and Possible Solutions	212
	References	217

Part II in this book is mainly soft materials sample preparation – i.e. quite useful for many of you

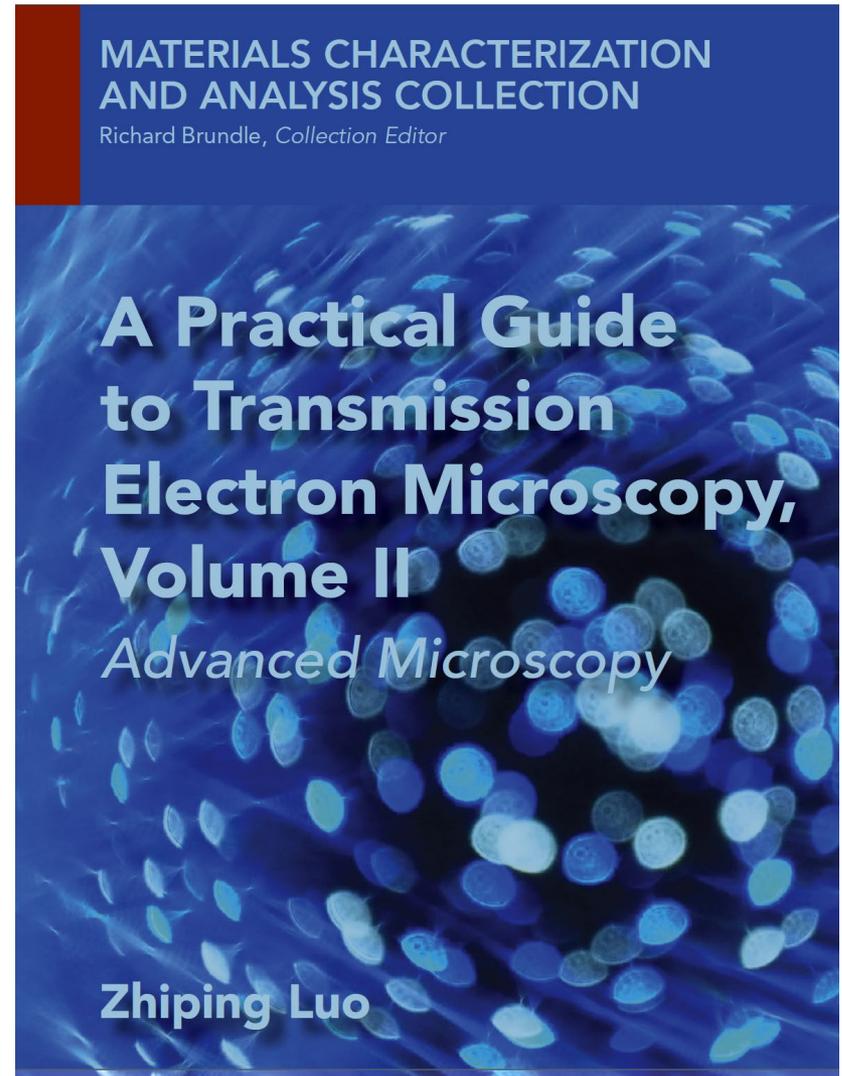
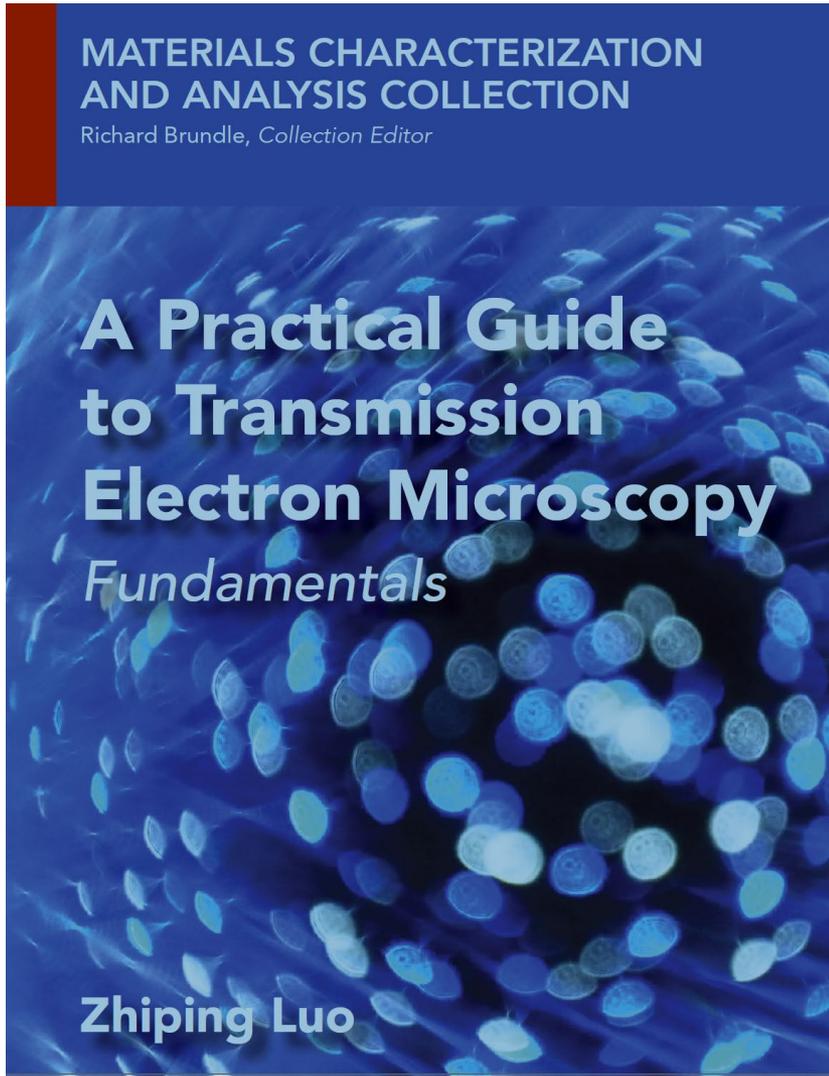
11	SPECIAL PREPARATION TECHNIQUES	219
11.1	Preparation of Polymer Films from Solutions	219
11.1.1	Introduction	219
11.1.2	Solution Behaviour of Polymers	220
11.1.3	Spin-Coating	220
11.1.4	Dip-Coating	222
11.1.5	Solution Casting	223
11.1.6	Examples and Problems	224
11.2	Preparation Using the Focussed Ion Beam Technique	227
11.2.1	Introduction	227
11.2.2	Principle	228
11.2.3	Examples	229
	References	230
12	PREPARATION FOR (IN SITU) DEFORMATION TESTS	231
12.1	Overview	231
12.2	Specimen Preparation	234
	References	240
13	CONTRAST ENHANCEMENT	241
13.1	Overview	241
13.2	Hardening (Fixation)	241
13.2.1	Physical Hardening (Fixation)	242
13.2.2	Chemical Fixation	243
13.3	Chemical Staining Procedures	243
13.3.1	Media Used to Perform Chemical Staining of Polymers	243
13.3.2	Chemical Staining of Compact Specimens Before Sectioning	246
13.3.3	Chemical Staining of Thin Sections	248
13.4	Enhancement of Contrast Through Physical Effects	248
13.4.1	Contrast Enhancement by γ - or Electron Irradiation	248
13.4.2	Straining-Induced Contrast Enhancement	254
13.5	Problems and Artefacts	256
	References	259

14	STRUCTURAL HIERARCHY OF POLYMERS	263
14.1	Overview	263
14.2	Macromolecular Structures	263
14.2.1	Constitution	265
14.2.2	Configuration	265
14.2.3	Conformation	265
14.2.4	Macromolecule Size	267
14.3	Supramolecular Structures	269
14.4	Morphology	271
14.5	Basic Relationships Between Macromolecular Parameters and (Micro)mechanical Properties	273
	References	276
15	AMORPHOUS POLYMERS	277
15.1	Overview	277
15.2	Morphology	277
15.3	Micromechanical Behaviour	281
15.4	Additional Examples of Amorphous Polymers	287
	References	293
16	SEMICRYSTALLINE POLYMERS	295
16.1	Overview	295
16.2	Morphology	296
16.2.1	Structural Hierarchy in Semicrystalline Polymers	296
16.2.2	Methods of Morphological Analysis	299
16.3	Micromechanical Behaviour	310
16.3.1	Brittle Behaviour	310
16.3.2	Ductile Behaviour	313
16.3.3	High-Strength Fibres and Parts	319
16.4	Additional Examples of Semicrystalline Polymers	321
	References	327
17	POLYMER BLENDS	329
17.1	Overview	329
17.2	Morphology	331
17.3	Micromechanical Behaviour	338
17.4	Examples	341
17.4.1	Blends of Amorphous Polymers	341
17.4.2	Blends of Amorphous and Semicrystalline Polymers	343
17.4.3	Blends of Semicrystalline Polymers	343
	References	349

Part III in this book is special applications for polymers – i.e. not the topic of this course..

18 HIGH-IMPACT RUBBER-MODIFIED POLYMERS	351
18.1 Overview	351
18.2 Morphology	352
18.3 Micromechanical Processes	357
18.4 Additional Toughening Mechanisms	368
References	370
19 BLOCK COPOLYMERS	373
19.1 Overview	373
19.2 Morphology	375
19.2.1 Block Copolymer Nanostructures via Self-Assembly	375
19.2.2 Examples of Tailored Block Copolymer Morphology	379
19.3 Deformation Mechanisms in Block Copolymers	385
19.4 Special Cases of Self-Assembly and Applications	389
References	391
20 RUBBERS AND ELASTOMERS	393
20.1 Overview	393
20.2 Morphology of Rubbers and Elastomers	395
20.3 Micromechanical Deformation Behaviour	398
References	402
21 POLYMER COMPOSITES	405
21.1 Overview	405
21.2 Particle-Reinforced Polymer Composites	406
21.3 Fibre-Reinforced Polymer Composites	414
References	417
22 POLYMER NANOCOMPOSITES	419
22.1 Overview	419
22.2 Examples of Different Classes of Nanocomposites	422
22.2.1 Polymer Nanocomposites Based on Zero-Dimensional Filler Particles (POSS)	422
22.2.2 Polymer Nanocomposites Based on One-Dimensional Filler Particles (MWCNT)	424
22.2.3 Polymer Nanocomposites Based on Two-Dimensional Filler Particles (MMT)	425
22.2.4 Polymer Nanocomposites Based on Three-Dimensional Filler Particles (SiO ₂)	427
References	428
23 BIOMATERIALS	429
23.1 Overview	429
23.2 Electron Microscopy of Polymeric Biomaterials: Specific Problems and Solutions	431
23.3 Examples	432
23.3.1 Natural Biomaterials: Bone	432
23.3.2 UHMWPE in Orthopaedics	433
23.3.3 Acrylic Bone Cements	434
23.3.4 Bioactive Composites for Bone Replacement	435
23.3.5 Dental Composites	436
23.3.6 Sutures, Scaffolds and Meshes	437
23.3.7 Ureter Stents	439
23.3.8 Silicone-Based Tracheal Stents and Voice Prostheses	439
References	443
24 SPECIAL PROCESSING FORMS	445
24.1 Overview	445
24.2 Multilayered Films	446
24.2.1 Introduction	446
24.2.2 Morphology	446
24.2.3 Micromechanical Deformation Mechanisms	448
24.3 Hot-Compacted Self-Reinforced Polymers	451
24.3.1 Overview	451
24.3.2 Morphology	452
24.4 Nanofibres by Electrospinning	455
24.4.1 Overview	455
24.4.2 Morphology	456
24.4.3 Micromechanical Deformation Mechanism	458
24.5 Microformed Materials	460
24.5.1 Overview	460
24.5.2 Several Examples	460
References	462
SUBJECT INDEX	465

Book 3: A Practical Guide to Transmission Electron Microscopy (2 parts)



Book 3: A Practical Guide to Transmission Electron Microscopy: **Fundamentals** (chapters 1,2,3)

Chapter 1	Introduction.....	1
	1.1 Microscope Resolution.....	2
	1.2 Interactions of Electrons with Specimen.....	4
	1.3 Comparison of TEM with Other Microscopy Techniques.....	6
	References.....	11
Chapter 2	Sample Preparation.....	13
	2.1 Material Samples.....	14
	2.1.1 TEM Grids.....	15
	2.1.2 Ion Milling.....	20
	2.1.3 Electropolishing.....	26
	2.1.4 Focused Ion Beam.....	30
	2.1.5 Microtomy.....	31
	2.2 Biological Samples.....	36
	2.2.1 Particulate Samples.....	37
	2.2.2 Cells and Tissue Samples.....	39
	References.....	42
Chapter 3	Instrumentation and Operation.....	45
	3.1 Construction.....	45
	3.1.1 Electron Gun.....	45
	3.1.2 Electromagnetic Lens.....	49
	3.1.3 Condenser Lenses and Condenser Apertures.....	52
	3.1.4 Objective Lens and Objective Aperture.....	55
	3.1.5 Intermediate Lens and Diffraction Aperture.....	57

	3.1.6 Projector Lens.....	59
	3.1.7 Viewing Screen and Camera.....	59
3.2	Instrument Imperfections, Alignments, Corrections, and Calibrations.....	60
	3.2.1 Beam Shift and Beam Tilt.....	60
	3.2.2 Spherical Aberration.....	61
	3.2.3 Chromatic Aberration.....	62
	3.2.4 Depth of Field and Depth of Focus.....	63
	3.2.5 Specimen Height.....	64
	3.2.6 Astigmatism.....	65
	3.2.7 Aperture Alignment.....	68
	3.2.8 Magnification Calibration.....	69
	3.2.9 Camera Length Calibration.....	71
	3.2.10 Magnetic Rotation Calibration.....	75
3.3	TEM Operating Procedures.....	76
	3.3.1 Startup.....	76
	3.3.2 Specimen Loading and Unloading.....	76
	3.3.3 Alignments.....	77
	3.3.4 Data Recording.....	78
	3.3.5 Finishing.....	78
	References.....	79
Chapter 4	Electron Diffraction I.....	81
	4.1 Formation of Electron Diffraction.....	82
	4.2 Reciprocal Space.....	84
	4.3 Indexing of Electron Diffraction Patterns.....	88
	4.3.1 Indexing of Powder Patterns.....	88
	4.3.2 Indexing of Single-Crystal Diffraction Patterns.....	90
	4.3.3 Indexing of Compound Patterns: Twins.....	92
	4.3.4 Indexing of Compound Patterns: Multiple Phases.....	96
	4.3.5 Indexing of Compound Patterns: Double Diffraction.....	98
	4.4 Experimental Procedures.....	101
	4.5 Simulation of Diffraction Patterns.....	103

References	105
Chapter 5 Imaging I.....	109
5.1 Imaging Contrast	109
5.2 Imaging with Mass-Thickness Contrast.....	110
5.3 Imaging with Diffraction Contrast	111
5.3.1 Formation of Diffraction Contrast.....	111
5.3.2 Central Dark-Field Imaging	114
5.3.3 Two-Beam Condition	115
5.3.4 Bragg-Diffracted Beam Intensity	117
5.3.5 Thickness Fringes.....	120
5.3.6 Bend Contours.....	122
5.3.7 Weak-Beam Dark-Field Imaging.....	122
5.3.8 Planar Defects	125
5.3.9 Dislocations.....	127
References	137
<i>And A Practical Guide to Transmission Electron Microscopy,</i>	
<i>Volume II Advanced Microscopy (chapters 7,8 and 9)</i>	
Chapter 6 Electron Diffraction II	
Chapter 7 Imaging II	21
7.1 STEM Imaging	21
7.1.1 Formation of STEM Images and Optics.....	21
7.1.2 STEM Experimental Procedures.....	24
7.1.3 STEM Applications.....	24
7.2 High-Resolution Transmission Electron Microscopy	28
7.2.1 Principles of HRTEM	28
7.2.2 Experimental Operations	37

7.2.3 Image Interpretation and Simulation	42
7.2.4 Image Processing	45
References	48
Chapter 8 Elemental Analyses	51
8.1 X-ray Energy-Dispersive Spectroscopy.....	52
8.1.1 Formation of Characteristic X-Rays	52
8.1.2 EDS Detector	54
8.1.3 EDS Artifacts.....	57
8.1.4 Effects of Specimen Thickness, Tilt, and Space Location	59
8.1.5 Experimental Procedures	63
8.1.6 EDS Applications	64
8.2 Electron Energy-Loss Spectroscopy.....	73
8.2.1 Formation of EELS.....	73
8.2.2 EELS Qualitative and Quantitative Analyses.....	75
8.2.3 Energy-Filtered TEM	78
8.2.4 EFTEM Experimentation and Applications	81
References	87
Chapter 9 Specific Applications	91
9.1 Quantitative Microscopy	92
9.1.1 Quantification of Size Homogeneity.....	92
9.1.2 Quantification of Directional Homogeneity	96
9.1.3 Dispersion Quantification	99
9.1.4 Electron Diffraction Pattern Processing and Refinement.....	103
9.2 <i>In situ</i> Microscopy	107
9.2.1 <i>In situ</i> Heating.....	108
9.2.2 <i>In situ</i> Cooling.....	114
9.2.3 <i>In situ</i> Irradiation.....	116
9.3 Cryo-EM.....	117
9.4 Low-Dose Imaging	122
9.5 Electron Tomography	125
9.5.1 Experimental Procedures	125
9.5.2 Object Shapes.....	127
9.5.3 Nanoparticle Assemblies.....	133
9.5.4 Nanoparticle Superlattices	135
References	143

PHYS-E0526 Microscopy of Nanomaterials, laboratory course P (5 cr)

Assistant: Shandilay Shruti and **other teachers:** Dr. Jani Seitsonen (TEM & Tomography), Dr. Hua Jiang (HR-TEM), Dr. Ramzy Abdelaziz (SEM), Dr. Lide Yao (FIB)

As practical exercises nanostructured materials are studied with various microscopy methods. Course includes practical microscopy exercises by using transmission electron microscopy (TEM), scanning electron microscopy (SEM) and Focused ion beam (FIB).

Number of students participating to the course will be limited. (max. ~18) Based on applications... nmc-contact-sci@aalto.fi Deadline 6. 2. 2023

Basic exercises – Demos:

(6 persons per group):

- 1) High resolution TEM (Jeol 2200FS Cs-corrected TEM)
- 2) 3D tomography data collection (Jeol 3200FSC liquid helium cryo TEM or Jeol2800) + Tomography data processing (Computer room)

Small group exercises: (Select 2)

(3 persons per group)

- 1) basic-TEM imaging
- 2) SEM imaging or
- 3) FIB -SEM processing/imaging

Independent Small group exercises (without supervision.. 3 person per group)

(2 exercises)

- 1) TEM imaging
- 2) SEM imaging
- 3) ...

To apply for the Laboratory Course – Answer the following questions just writing a short email and send it to the nmc-contact-sci@aalto.fi deadline Friday 6. 2. 2023

1. You are a *

- graduate student
- exchange student
- Ph.D student
- post doc/other

2. Your primary affiliation is *

- Aalto University
- University of Helsinki
- VTT
- Other

3. Do you belong to a research group? If yes, who is your supervisor/instructor?

Research Group

Supervisor/Instructor

4. Write with your own words your primary motivation to participate on the laboratory course. *

5. What instrument do you plan to use in your research?

- AFM
- SEM
- TEM
- HRTEM
- Cryo-TEM
- TEM tomography
- XRAY

6. Contact Information

Firstname *

Lastname *

Email *

Student Number (if you have one)

Exam for lecture course PHYS-E0525 Microscopy of Nanomaterials...

We have multiple choice questions from TEM, SEM, FIB, AFM etc..

+ some normal questions – where you write short answers

TEM Questions

1. What is STEM?

- Scanning transmission electron microscopy
- Standard transmission electron microscopy
- Scanning and transmission electron microscopy
- Suitable transmission electron microscopy
- Scanning tunneling electron microscopy

2. Bright field TEM is best described as?

- Microscopy where the electron beam is well aligned
- The exclusion of the scattered electron beam while the beam is directed onto the sample
- Any imaging that must be undertaken in a well lit room
- The exclusion of the central beam electrons by tilting the beam, displacing the objective aperture or introducing the beam stop
- Microscopy where the filament has not broken

3. How can chromatic aberrations be minimized in a TEM?

- Use an electron gun with high energy spread and a thin specimen
- Use an electron gun with low energy spread and a thick specimen
- Use an electron gun with high energy spread and a thick specimen
- Use an electron gun with medium energy spread and a thick specimen
- Use an electron gun with low energy spread and a thin specimen



Aalto University
School of Science
and Technology

Nanomicroscopy center

Prof. Janne Ruokolainen Director 2005 - 2020

New manager Jani Seitsonen 1. 1. 2021 →

Aalto University, Otanano





Introduction

*The new Nanomicroscopy Center is large **microscopy clusters** (even compared to other European centers). The center is now housing various microscopes able to characterize **hard materials down to atomic resolution**, and **soft materials including biomaterials down to molecular resolution**.*

- Started in operation 2008 →
- Center area 1220 m² / 740 m²
- Center for various different *high resolution microscopy* techniques (currently >10 different high-resolution microscopes: **5 TEM's**, **3 SEM's**, AFM's, 3 STM's.. + New **FIB-SEM** 2019)
- Instrument investments (until now..) >15 M€

Key Instruments:

- First lens *aberration corrected* transmission electron microscope in Finland with approximately 1 Å resolution (*JEOL 2200FS*)
(new 300 kV microscope will replace this 2024)
- First *Liquid helium cryo*-transmission electron microscope in Finland (operating at -255 °C or -187 °C) (*JEOL 3200FSC*)

Equipment and their new values, and purchase years

Transmission electron microscopes (TEM)

	Value	Year
1) 120kV TEM Tecnai 12	350 k€	2004
2) Double Cs corrected sub-Ångstrom 200kV (S)TEM, EDX, EELS	>2000 k€	2009
3) Liquid Helium 300kV cryo-TEM, EELS	>2000 k€	2009
4) 200kV FEG (S)TEM , EDX	>1300 k€	2016
5) 200kV FEG TEM (moved from Department of Materials Science and Engineering 2016)		

Scanning electron microscopes (SEM)

1) JEOL 7500F FEG-SEM + EDX	400 k€	2008
2) Zeiss Sigma FEG-SEM +EDX (2021)	300 k€	2011
3) Zeiss E-SEM	150 k€	2011
4) dual beam FIB-SEM (EDX, EBSD, Cryo-SEM 2021)	~1400 k€	2019

Scanning probe microscopy (AFM, STM)

1) Veeco Dimension 5000 AFM	300 k€	2008
2) RHK UHV-750 variable temperature STM (UHV-STM)	500 k€	2005 - 2009
3) Createc LT-STM low-temperature STM	460 k€	2012
4) cryo UHV-STM	580 k€	2012

X-ray Scattering

1) Small Angle X-ray Scattering (SAXS)	550 k€	2006 - 2008
2) Wide and Medium Angle X-ray Scattering (WAXS/MAXS)	450 k€	2008 – 2016
3) 2D-microfocus XRD	500 k€	2016
4) New-SAXS small angle X-ray setup	500 k€	2020

sample preparation equipment etc.

Cryo vitrification (3), ultra microtoming (2), ion-milling, polishing, plasma cleaner...

TEM holders, cross section polisher,, ...

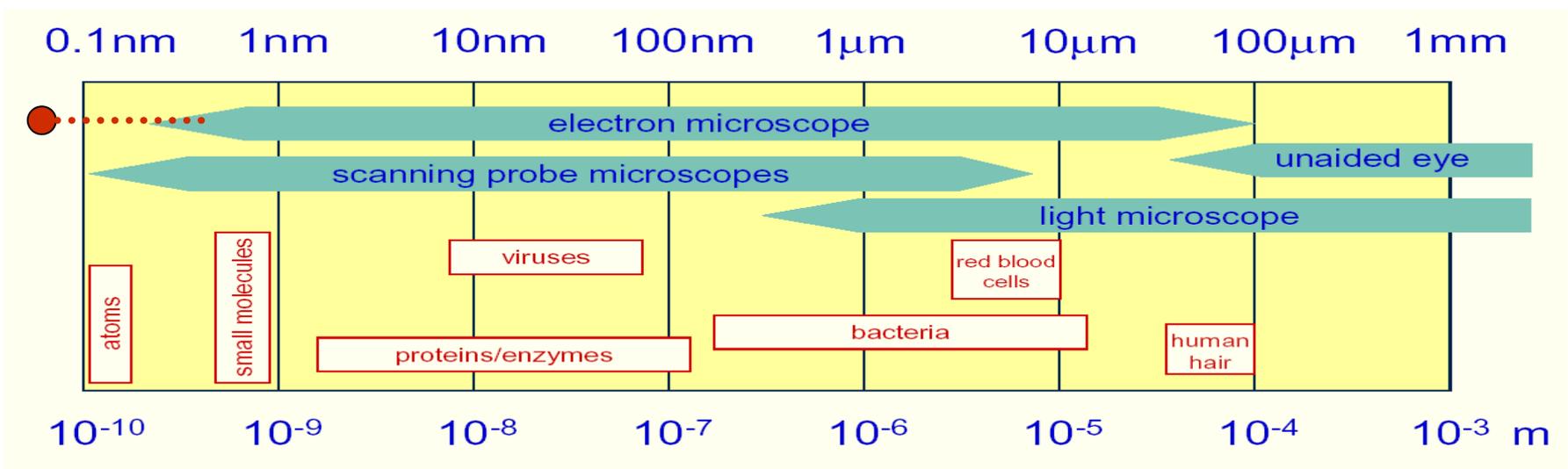
2000 k€ 2009 -

Total: >15 M€

Microscopy Resolution – Different Microscopes

SEM from cm scale → up to sub nanometer resolution

TEM from micrometer scale → up to sub Ångström resolution



Nanoparticles, carbon nanotubes
 Lipids, polymer-amphiphile, liquid crystals
 Block copolymers
 Polymer blends, colloids...

0.1 nm –
 1 – 10 nm
 10 – 100 nm
 50 nm – 10 μm

Electron microscope resolution:

In ideal case:

Theoretical resolution $r_{th} = \frac{0.61 * \lambda}{\mu \sin \beta} \approx \frac{0.61\lambda}{\beta}$
 (Classical Rayleigh criteria)

Light microscope wavelength $\sim 400 - 600 \text{ nm}$

Electron wavelength 300 kV $\sim 0.002 \text{ nm} !!!$

Spherical aberration $r_{sph} = C_s \beta^3$

Chromatic aberration $r_{chr} = C_c \frac{\Delta E}{E_0} \beta$

Example Jeol 3200FSC cryo-TEM:

300 kV, $C_s = 4.1 \text{ mm}$, $C_c = 3.4 \text{ mm}$

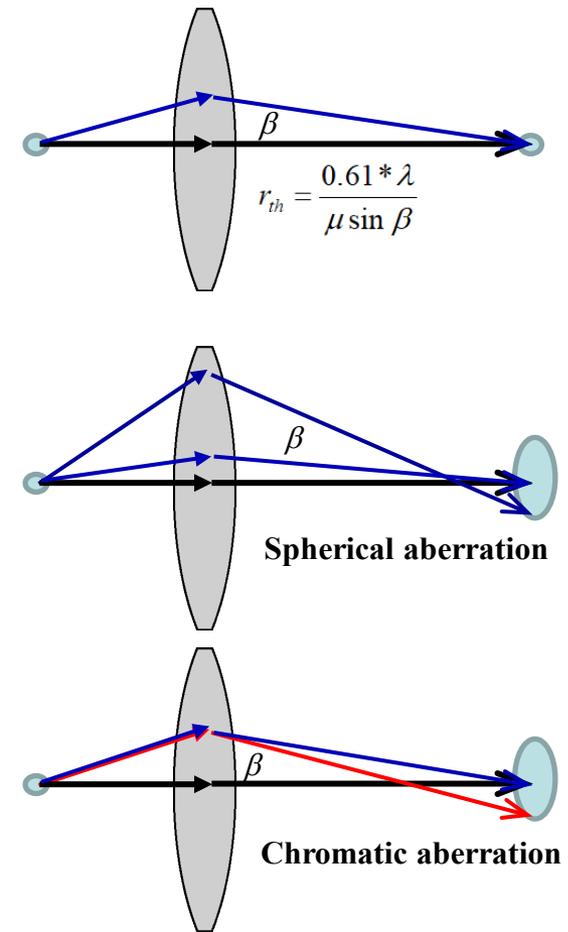
\rightarrow point resolution $\sim 2.6 \text{ \AA}$

Jeol 2200FS $C_s = 1.0 \text{ mm}$ $C_c = 1.4 \text{ mm}$, 200kV

Point resolution 2.3 \AA (without C_s correctors)

Jeol 2800 200kV $C_s = 0.7 \text{ mm}$

Point resolution 2.0 \AA



$$r_{total} = \sqrt{(r_{th})^2 + (r_{sph})^2 + (r_{chr})^2 + \dots}$$

If spherical aberration could be corrected

$C_s \sim 0 \rightarrow$ resolution $< 1 \text{ \AA}$

If also chromatic aberration could be corrected or minimized \rightarrow resolution $< 0.5 \text{ \AA}$

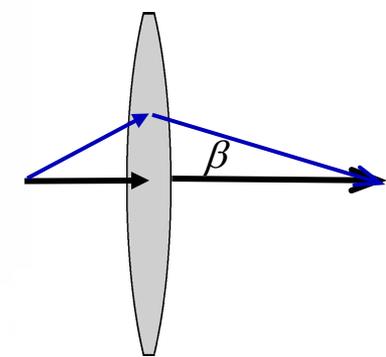
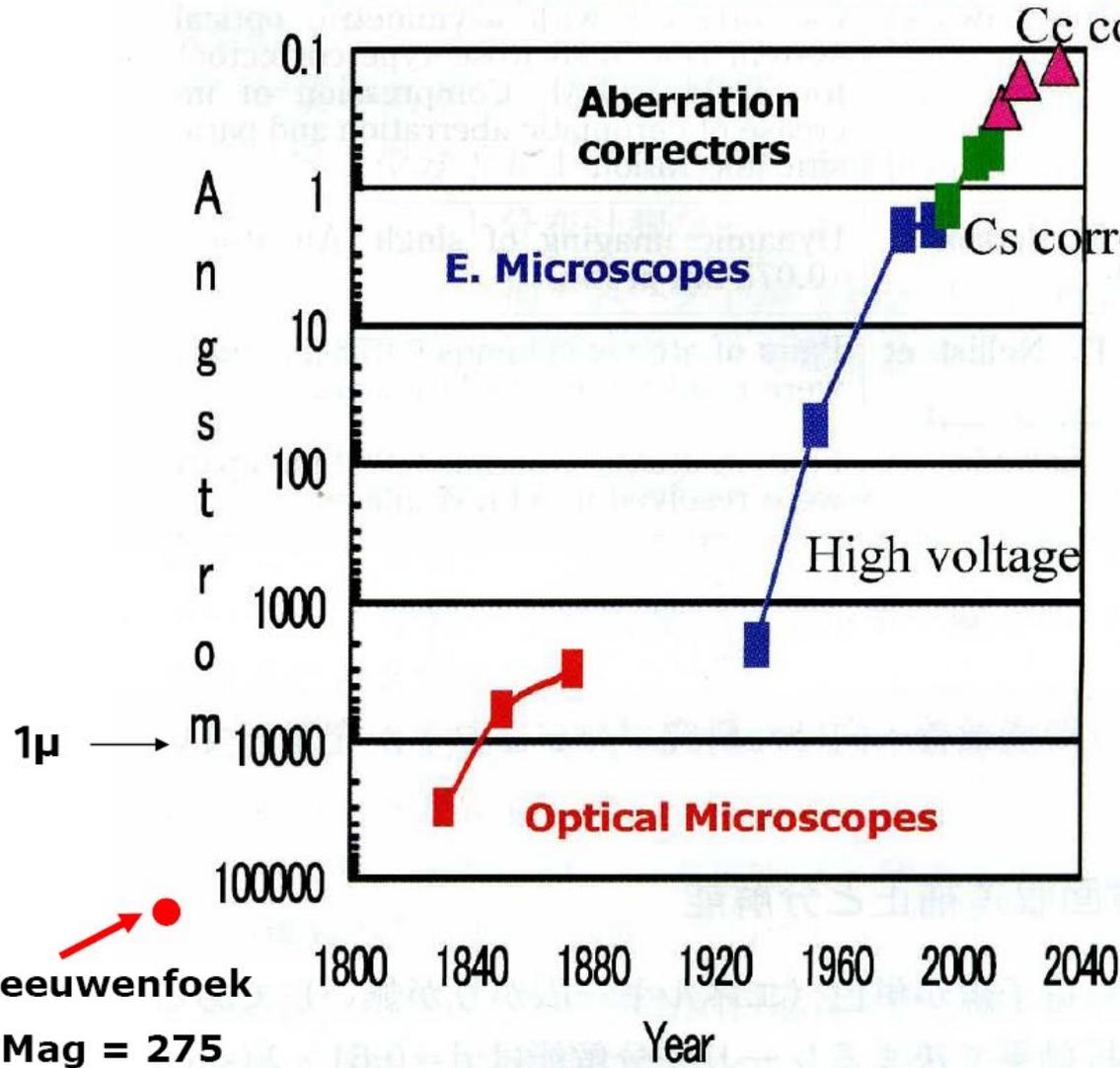
Spherical aberration in **Hubble Space Telescope**



Analysis of the flawed images showed that the cause of the problem was that the primary mirror had been ground to the wrong shape. Although it was probably the most precisely figured mirror ever made, with variations from the prescribed curve of only 10 nanometers, it was **too flat at the edges by about 2200 nanometers (mirror diameter 2.4 meters..)**. This difference was catastrophic, introducing severe spherical aberration a flaw in which light reflecting off the edge of a mirror focuses on a different point from the light reflecting off its center.

Progress of microscopes since 18 century

We stand now at a nanoworld of 0.4 \AA (40pm)



Resolution

$$r_{th} = \frac{0.61 * \lambda}{\mu \sin \beta}$$

(after Takayanagi)

Year 1676

Ernst Ruska and Max Knoll built the first electron microscope in 1931 (Nobel Prize to Ruska in 1986)

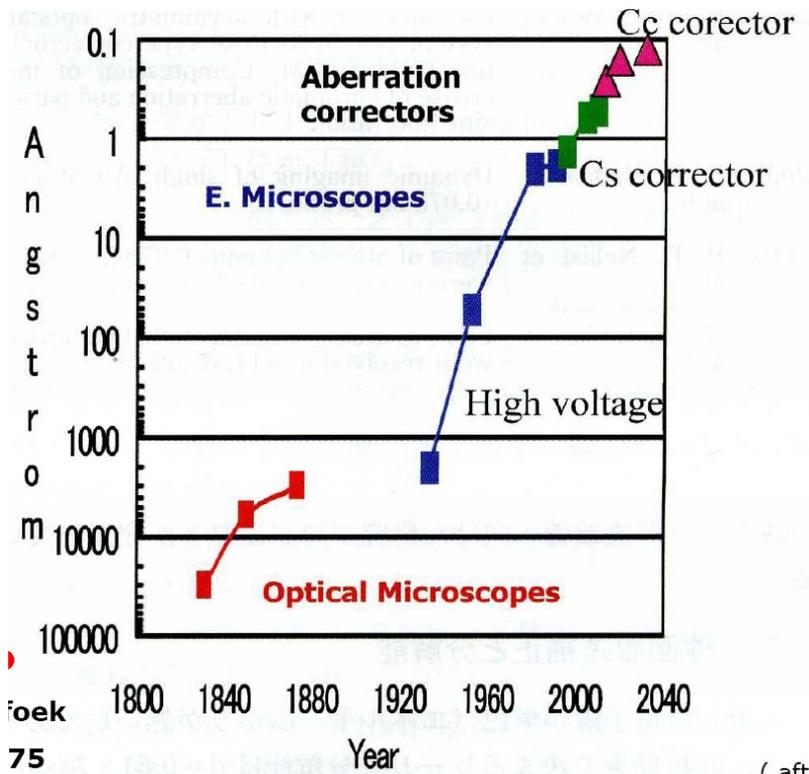


TABLE 1.2 Electron Properties as a Function of Accelerating Voltage

Accelerating voltage (kV)	Non-relativistic wavelength (nm)	Relativistic wavelength (nm)	Mass ($\times m_0$)	Velocity ($\times 10^8$ m/s)
100	0.00386	0.00370	1.196	1.644
120	0.00352	0.00335	1.235	1.759
200	0.00273	0.00251	1.391	2.086
300	0.00223	0.00197	1.587	2.330
400	0.00193	0.00164	1.783	2.484
1000	0.00122	0.00087	2.957	2.823

FIGURE 1.1. The electron microscope built by Ruska (in the lab coat) and Knoll, in Berlin in the early 1930s.

High voltage TEM (typically 400 kV -3 MV)

In early years the resolution was increased by using higher voltage TEM - since the wavelength is smaller and therefore resolution is potentially better..

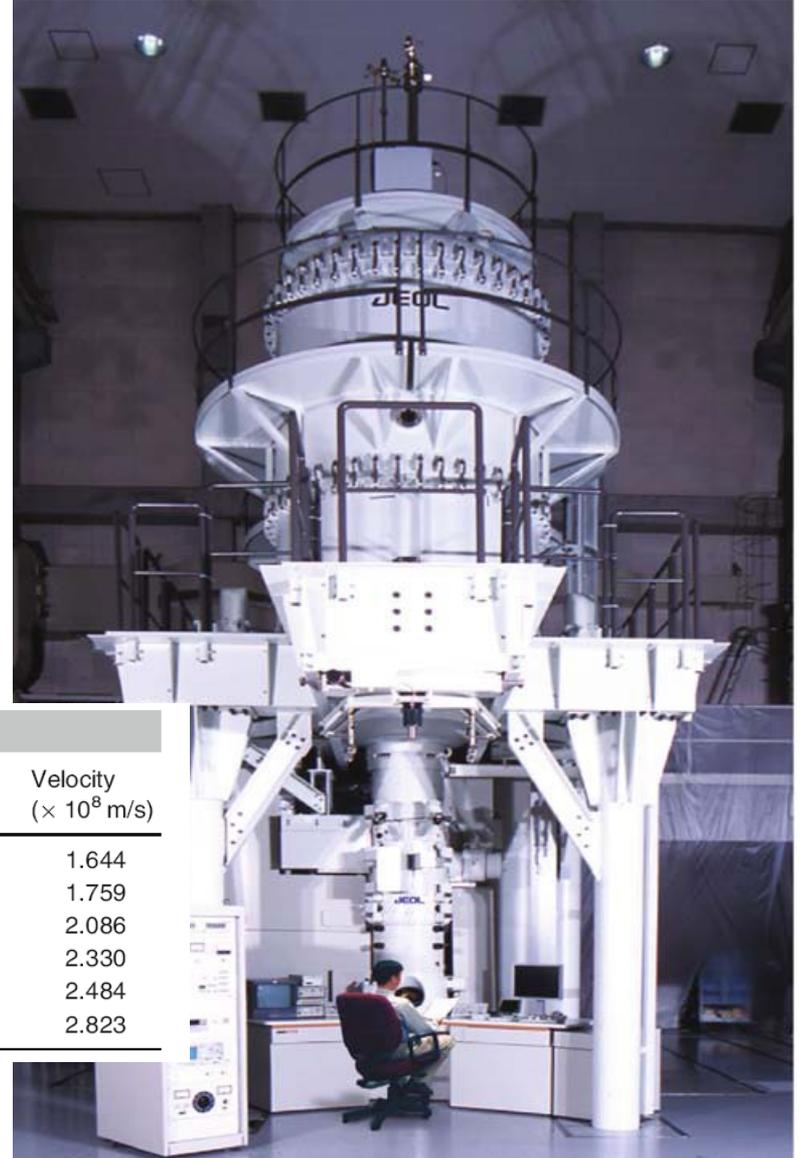
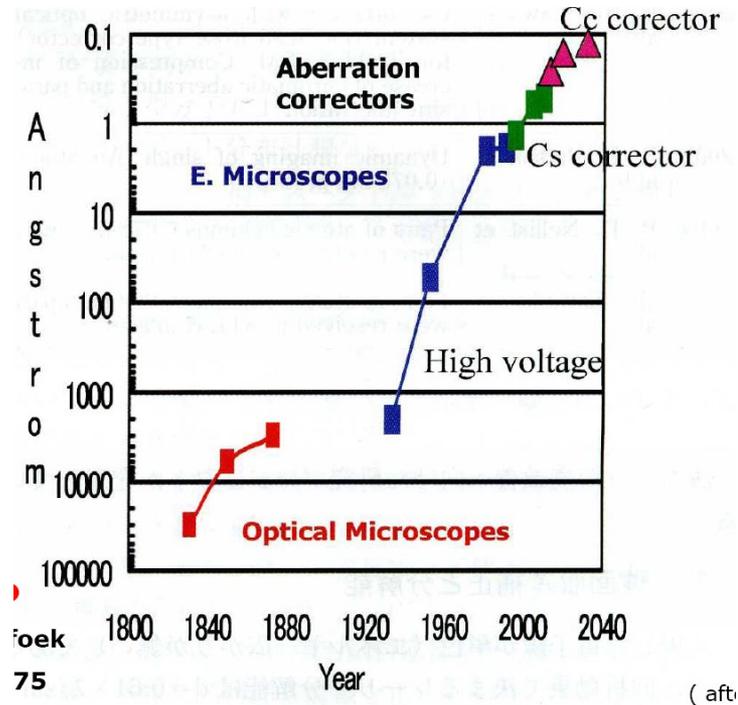


TABLE 1.2 Electron Properties as a Function of Accelerating Voltage

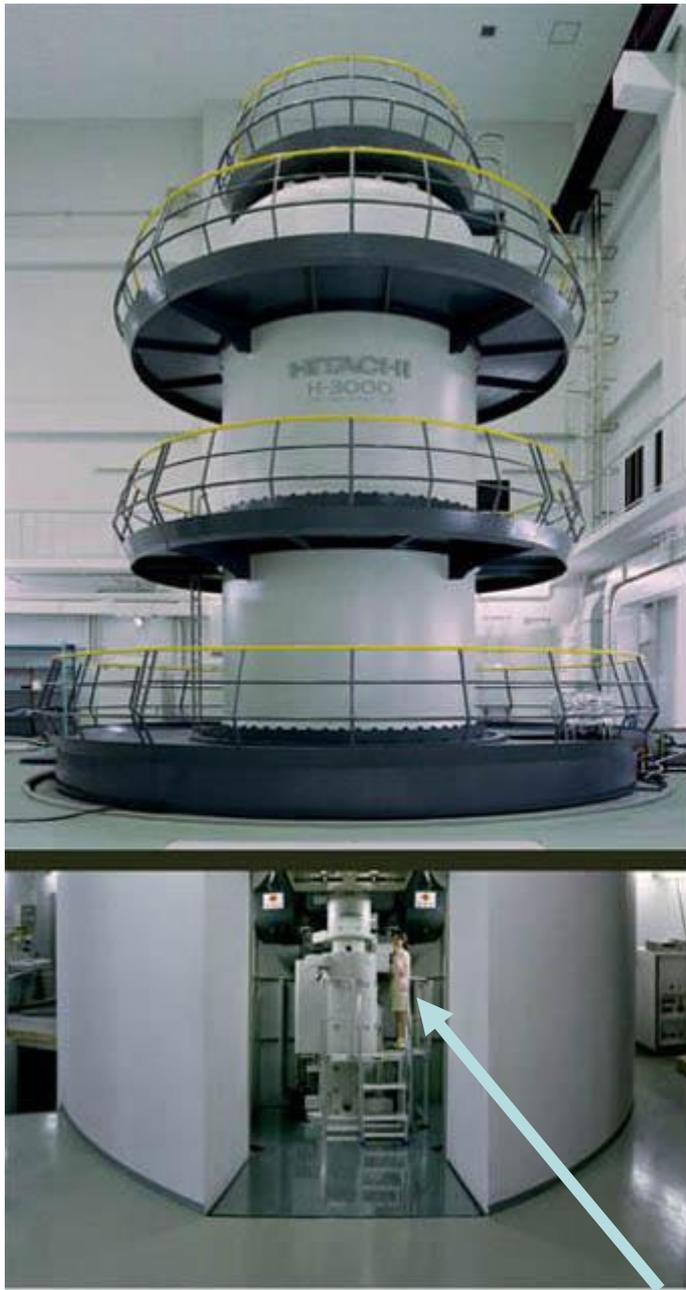
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400	0.00193	0.00164	1.783	2.484
1000	0.00122	0.00087	2.957	2.823

$$r_{th} = \frac{0.61 \cdot \lambda}{\mu \sin \beta} \approx \frac{0.61 \lambda}{\beta} \quad (\text{in TEM } \beta \text{ is small})$$

Nowadays these high voltage TEM's are mostly used for material radiation damage research and some special applications where thick samples are required for imaging (high voltage electrons can penetrate thicker samples .. i.e even some micrometer thick samples .. Normal TEM's require typically <100 nm or even < 10 nm samples for high resolution work



Hitachi 3.5MeV (S)TEM

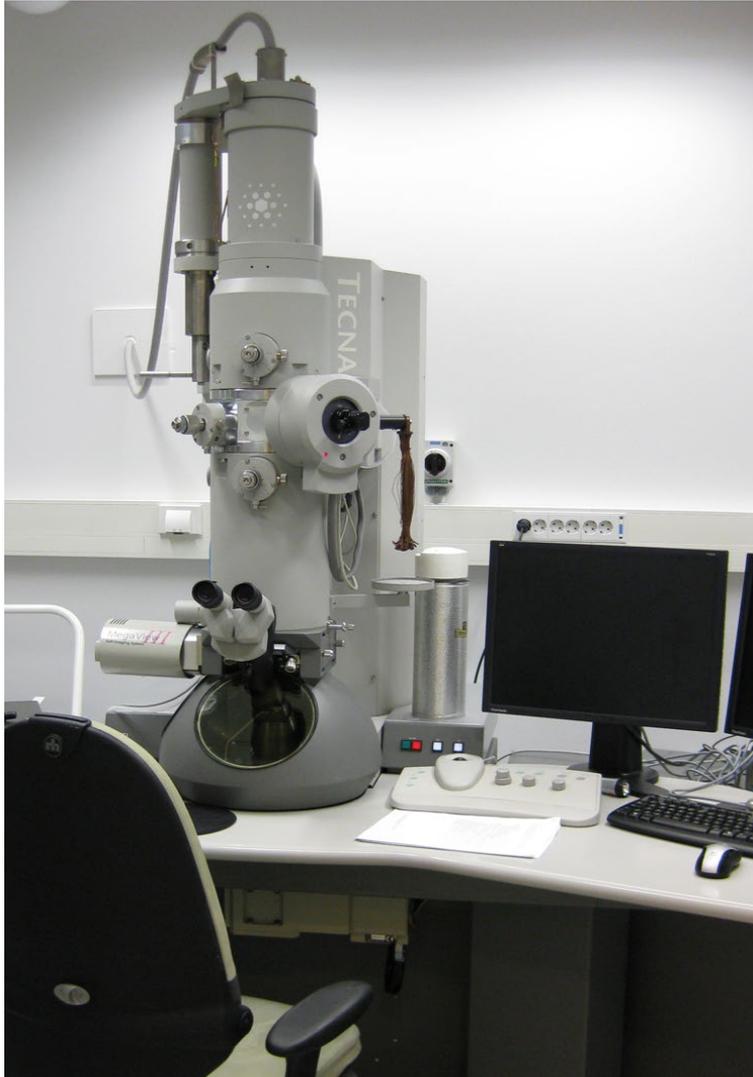


Microscopes are quite big - Notice the operator standing there..

Base F

In NMC we have 4 (5) TEM's

In this picture the two oldest TEM's 120 kV TEM and 200 kV TEM are shown

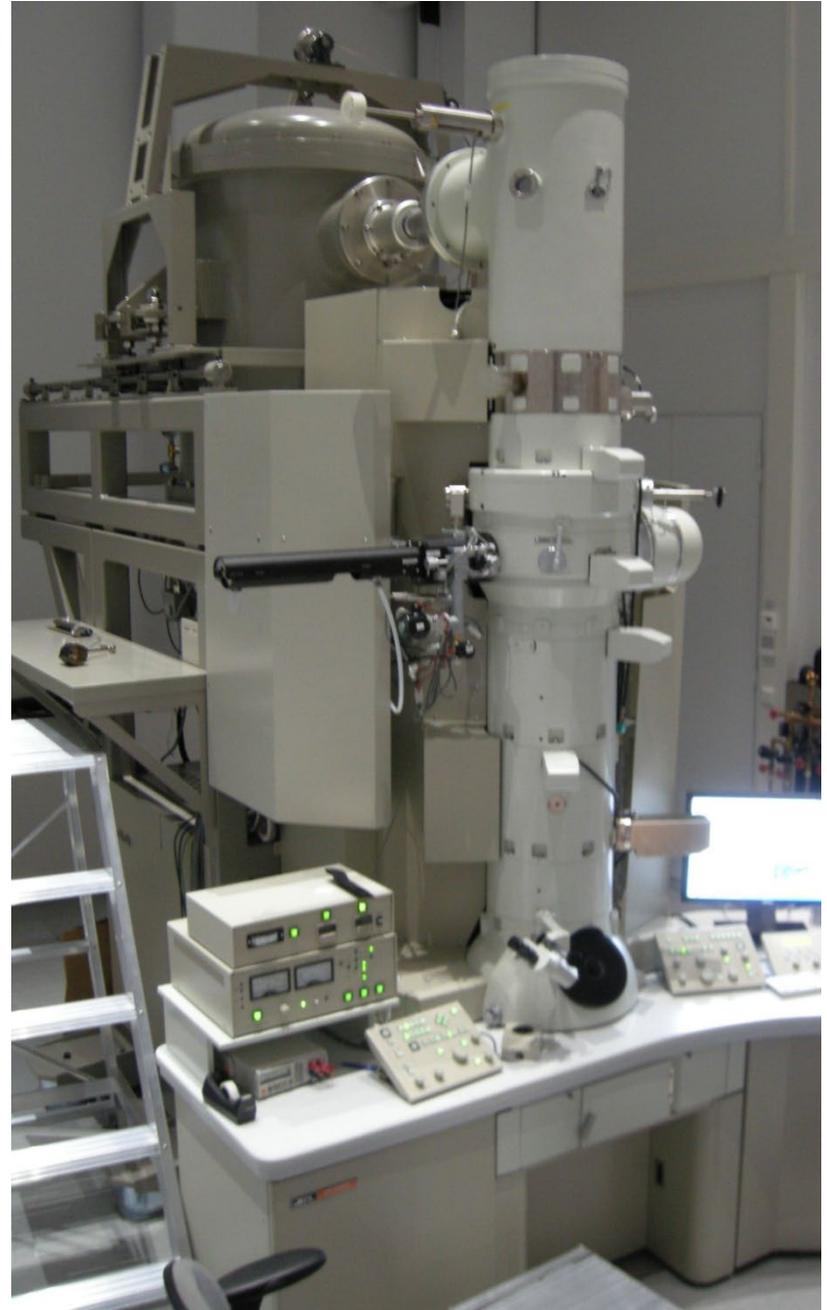


FEI Tecnai T12 Installation 2003
(Will be replaced with new 200kV TEM in 2024)



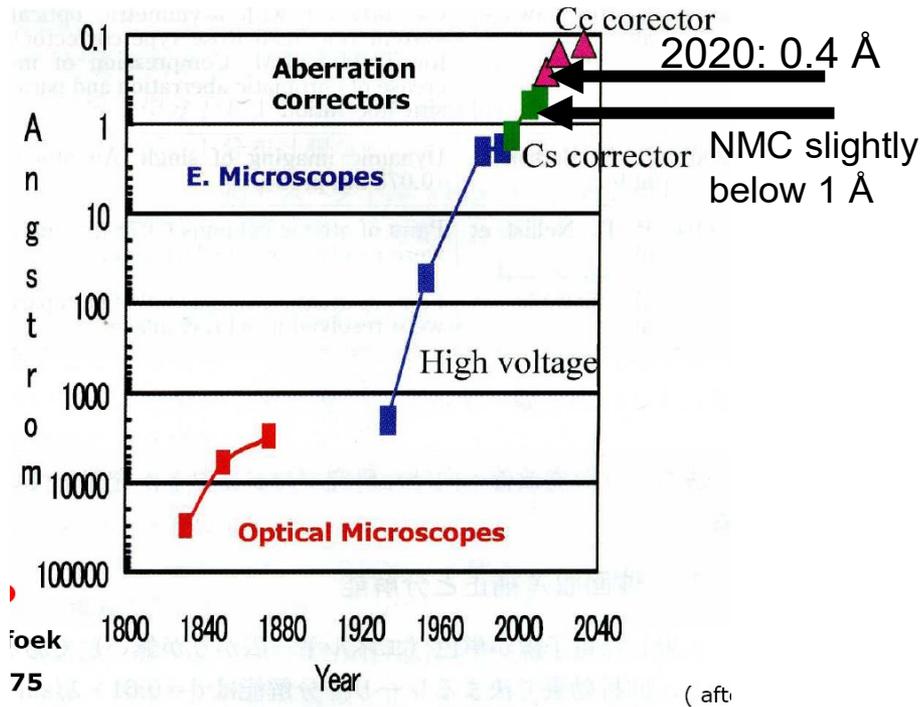
FEI Tecnai F20 Installation 1999? (Material science laboratory (Chem) and 2016 → moved to NMC)
(now permanently broken... and will be thrown away..)

NMC: newest 200 kV TEM and 300 kV Cryo-TEM



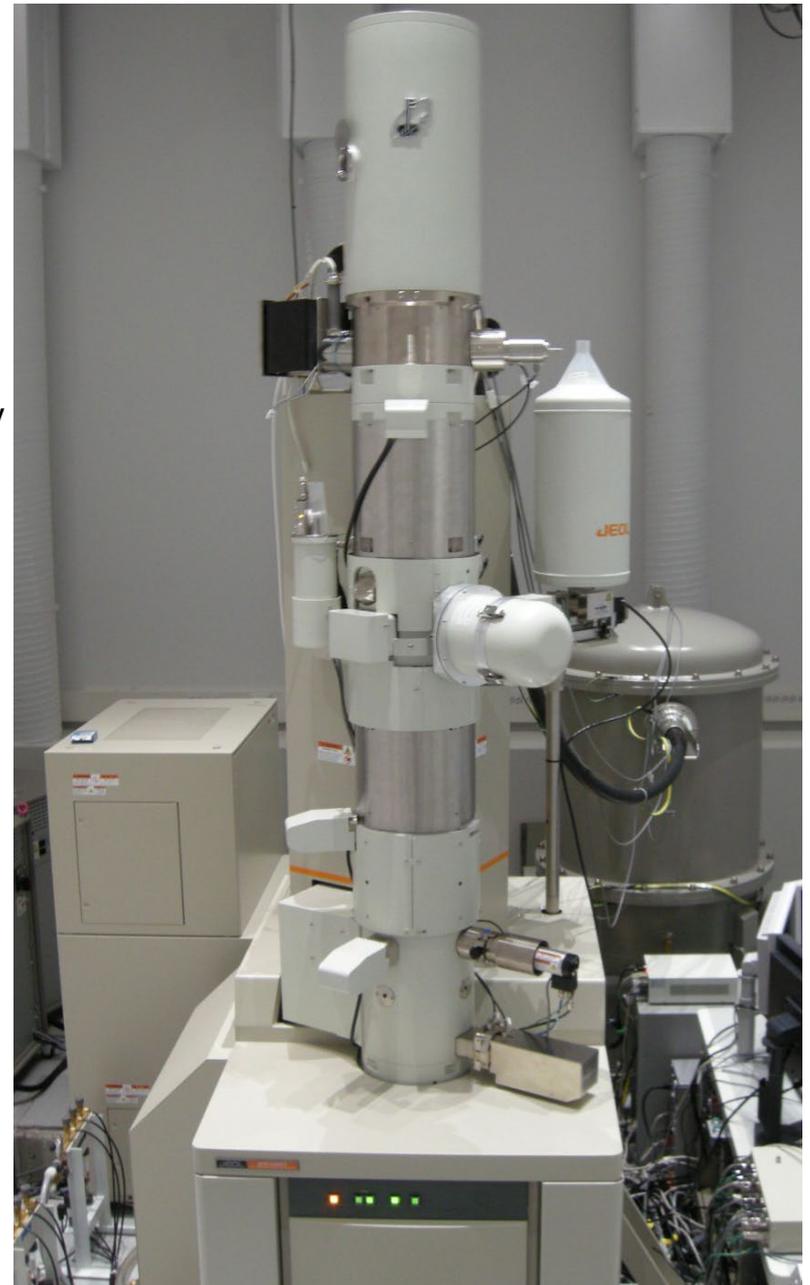
NMC highest resolution Double Cs-corrected (S)TEM

(to be replaced with new 300 kV TEM in 2024)

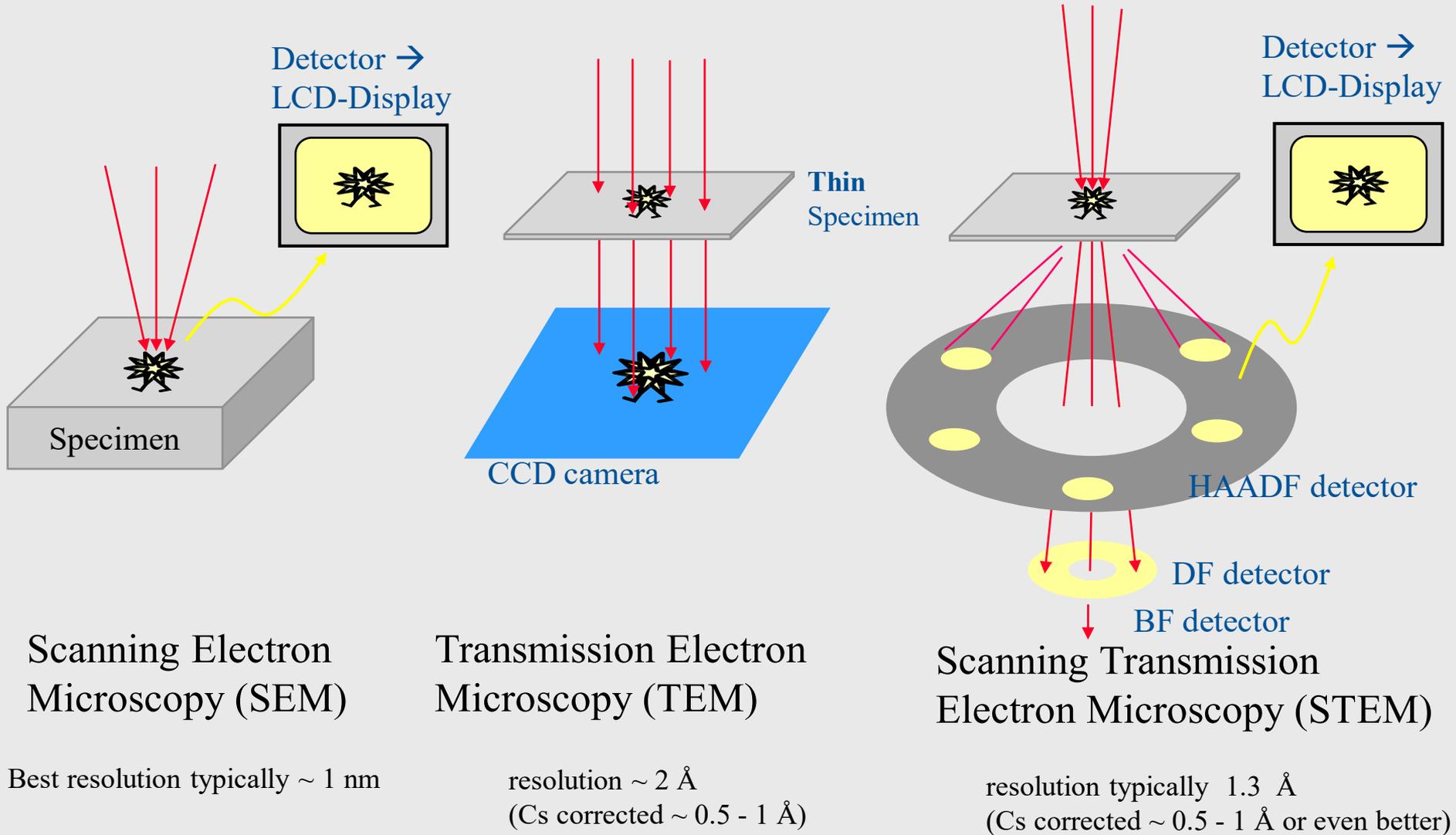


Installation 2009: TEM and STEM resolution slightly below 1 Å

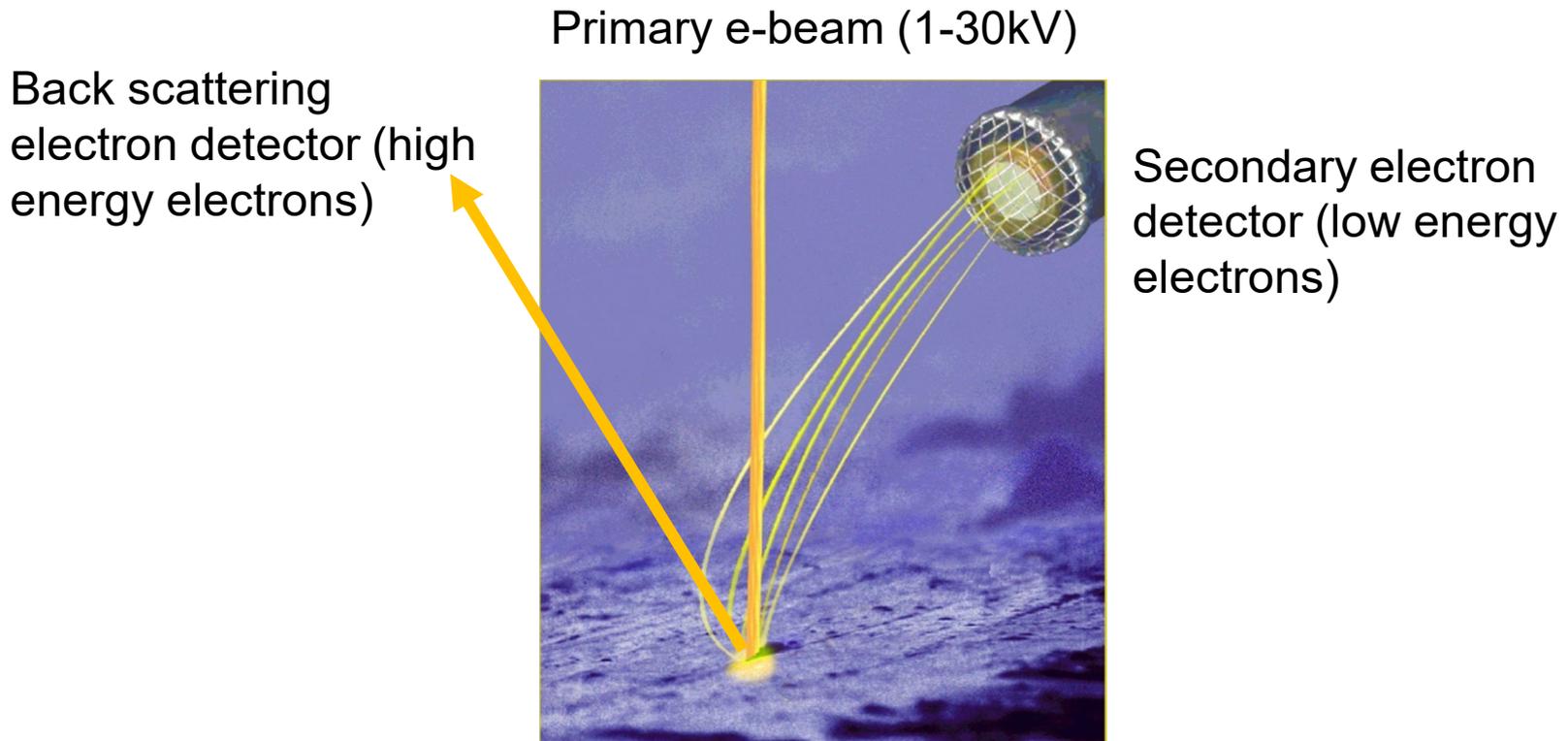
Now best resolution for commercial microscopes is 0.4 Å



Brief introduction to the electron microscopy



Scanning Electron Microscopy (SEM)



The scanning electron microscope (SEM) uses a focused beam of high-energy electrons (typically 1kV to 30 kV) to generate a variety of signals at the surface of solid specimens. The signals that derive from electron-sample interactions reveal information about the sample morphology (texture), chemical composition, and crystalline structure and orientation of the materials. Electron beam is scanned across the surface point by point and each point signal is collected, and 2-dimensional image is generated.

Scanning Electron Microscopy (SEM)

Surface technique:

- Relatively high resolution –
Best case even $<1\text{nm}$ (0.4 nm)
 - Large depth of field (Large sample focus range)
 - Low and high magnifications
 - Large samples
 - Possibility to microanalysis (EDX)
 - Relatively easy sample preparation
(normally thin metal coating needed - gold/palladium, platinum, carbon, etc.)
-
- Samples in vacuum (same as TEM)
 - Limited to surface studies (except if STEM option is available – but then very thin samples needed... since voltage is max. 30 kV)



SEM examples: Fly head and leg



Large depth of field: sample is focus on different heights at the same time



passion flower



Nanomicroscopy center has 3 SEM's

1.)

This SEM has been the primary training and research SEM at NMC since 2008.



JEOL JSM-7500FA Information Card

<i>Manufacturer</i>	JEOL
<i>Model</i>	JSM-7500F (later upgraded to JSM-7500FA)
<i>Emitter</i>	Cold FEG
<i>Installation</i>	2008
<i>Detectors</i>	In-column SE ETSE BSE (2 segment) EDX (JEOL)
<i>Resolution</i>	0.6 nm @ 30 kV 1.4 nm @ 1 kV
<i>Acceleration voltage</i>	0.1 - 30 kV
<i>Probe current</i>	-
<i>Operating modes</i>	High vacuum (10^{-5} Pa)
<i>Stage</i>	Motorized 5 axis (compucentric) X & Y 50 mm Z 25 mm T -5 - 70° R 360°
<i>Specimen size</i>	max. 100 mm diameter max. 10 mm height

This SEM is going to be the primary training SEM for Nanomicroscopy Center SEM users.

2.)



Zeiss Sigma VP Information Card

<i>Manufacturer</i>	Zeiss
<i>Model</i>	Σigma VP
<i>Emitter</i>	Schottky FEG
<i>Installation</i>	2011
<i>Detectors</i>	In-column SE ETSE BSE (5 segment) VPSE STEM
<i>Resolution</i>	1.3 nm @ 20 kV 2.8 nm @ 1 kV 2.5 nm @ 30 kV (VPSE)
<i>Acceleration voltage</i>	0.1 - 30 kV
<i>Probe current</i>	4 pA - 20 nA
<i>Operating modes</i>	High vacuum (10⁻⁵ Pa) Variable pressure (2 - 133 Pa, N₂)
<i>Stage</i>	Motorized 5 axis (compucentric) X & Y 125 mm Z 50 mm T -10 - 90° R 360°
<i>Specimen size</i>	max. 250 mm diameter max. 145 mm height

0.02 – 1.3 mbar
This mode we can reduce the charging effects for non conducting samples and even do imaging without metal/carbon coating

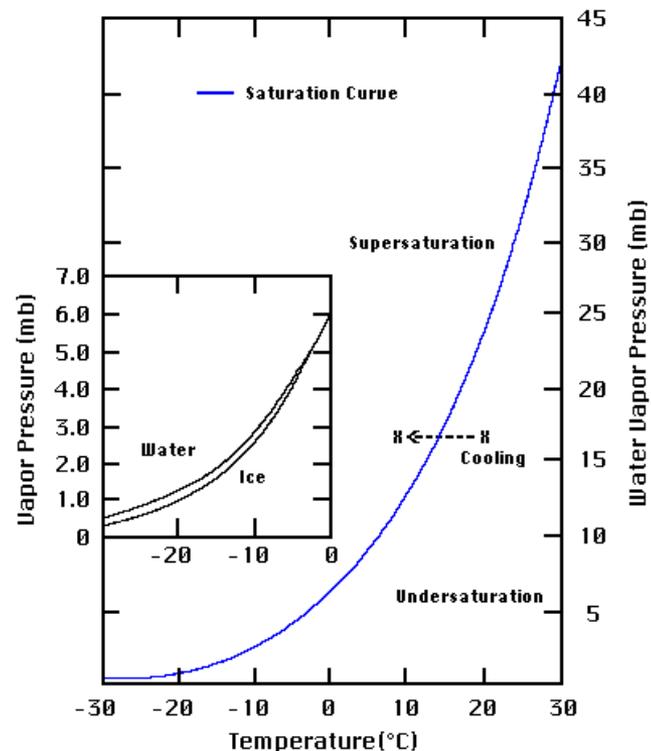
3.)



Zeiss EVO HD15 Information Card

Manufacturer	Zeiss
Model	EVO HD15
Emitter	LaB ₆ with "HD" technology
Installation	2011
Detectors	ETSE BSE (5 segment) VPSE EPSE STEM
Resolution	1.9 nm @ 30 kV 3 nm @ 30 kV (1 nA) 5 nm @ 3 kV 8 nm @ 1 kV 3 nm @ 30 kV (VPSE)
Acceleration voltage	0.2 - 30 kV
Probe current	0.5 pA - 1 uA
Operating modes	High vacuum (10 ⁻⁵ Pa) Variable pressure (10 - 133 Pa, N ₂ , air, H ₂ O) Extended pressure (10 - 3000 Pa, N ₂ , air, H ₂ O)
Stage	Motorized 5 axis (compucentric) X & Y 125 mm Z 50 mm T -10 - 90° R 360°
Specimen size	max. 250 mm diameter max. 145 mm height

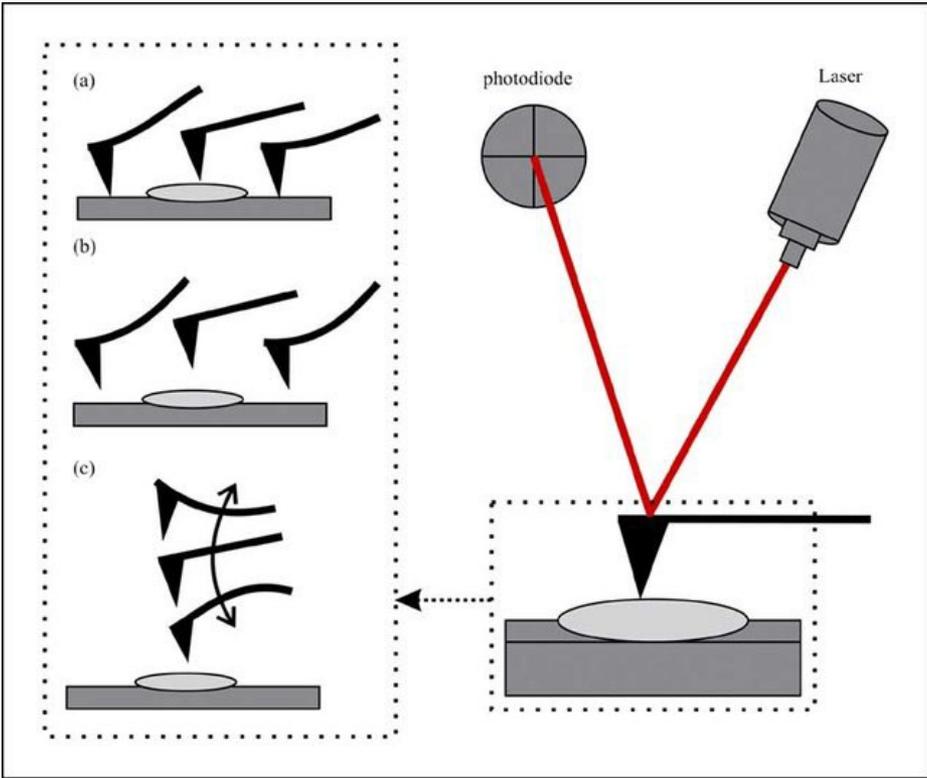
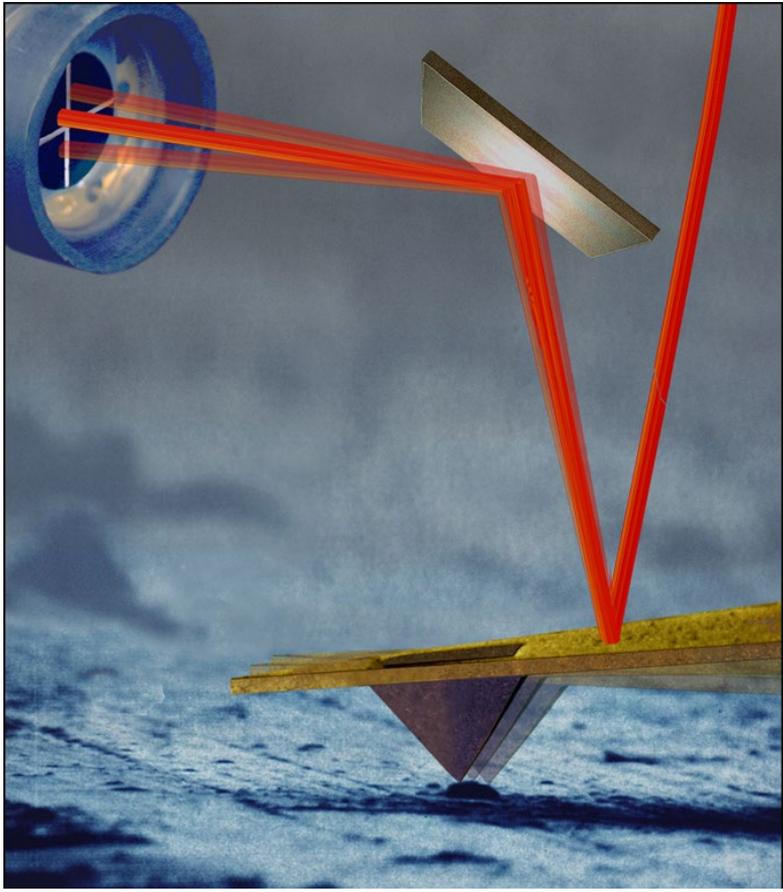
The vapor pressure of ice and water between -30° and 30° (mb = millibar). (Berner and Berner 1987)



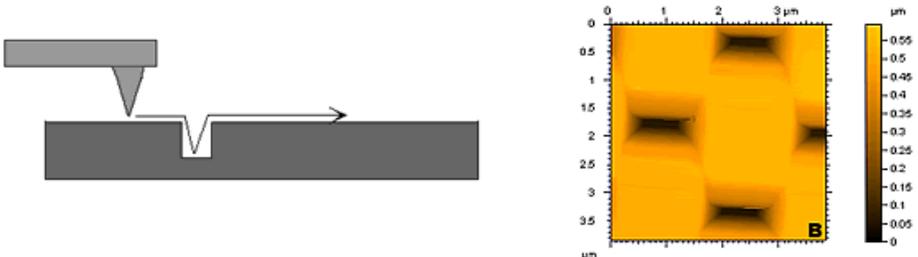
0.1 – 30 mbar
Typical working conditions for water containing samples are close to 0 degrees Celsius and 6 mbar pressures

Scanning probe microscopy (SPM) historically called AFM)

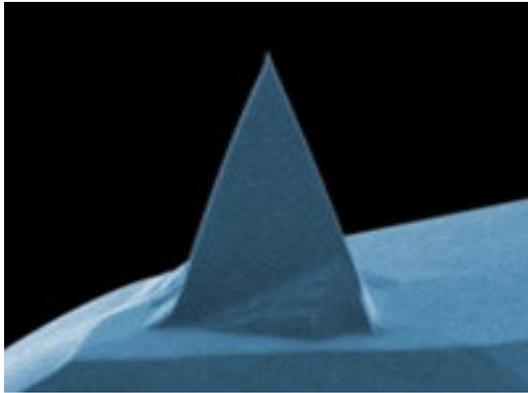
- a) Contact mode
- b) Non-contact mode
- c) Tapping mode (tip is oscillating on surface)



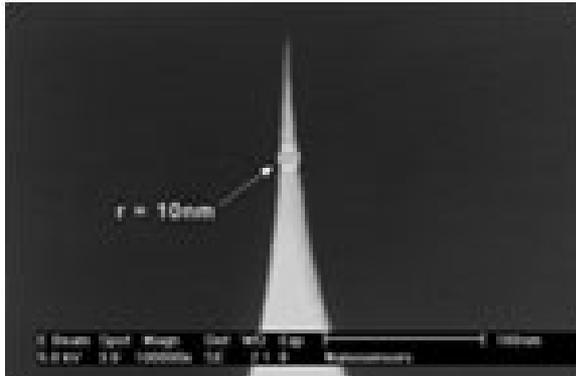
In AFM we use sharp tip to scan the sample surface to obtain information about surface topography and other properties (chemical, mechanical hardness, electrical etc.)



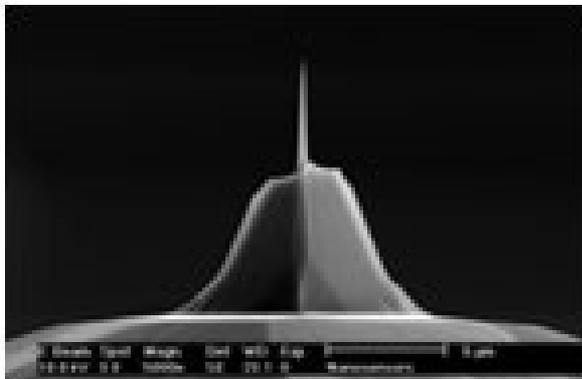
Examples AFM probes



Standard Tip radius typically 8-10 nm
(cost 10 -20 euros per each)



Super sharp tips: Tip radius is typically 1nm (~100 €)



High aspect ratio tips:
The length of the high aspect portion of the tip is larger than $1.5\ \mu\text{m}$

NMC instruments:

AFM: Veeco Dimension 5000 SPM (installed 1/2008)



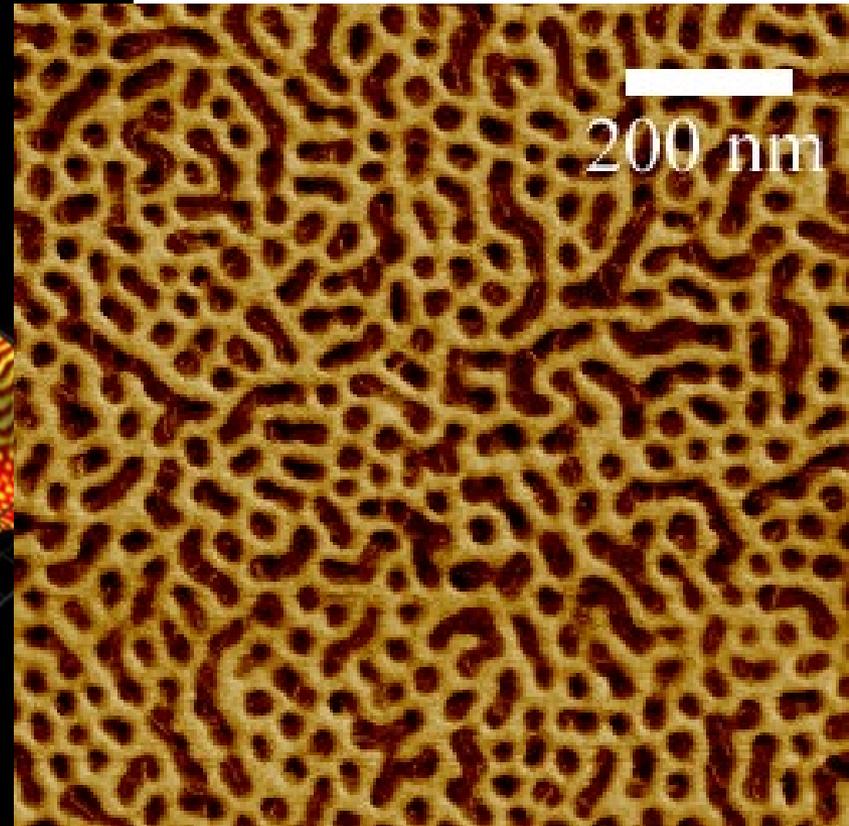
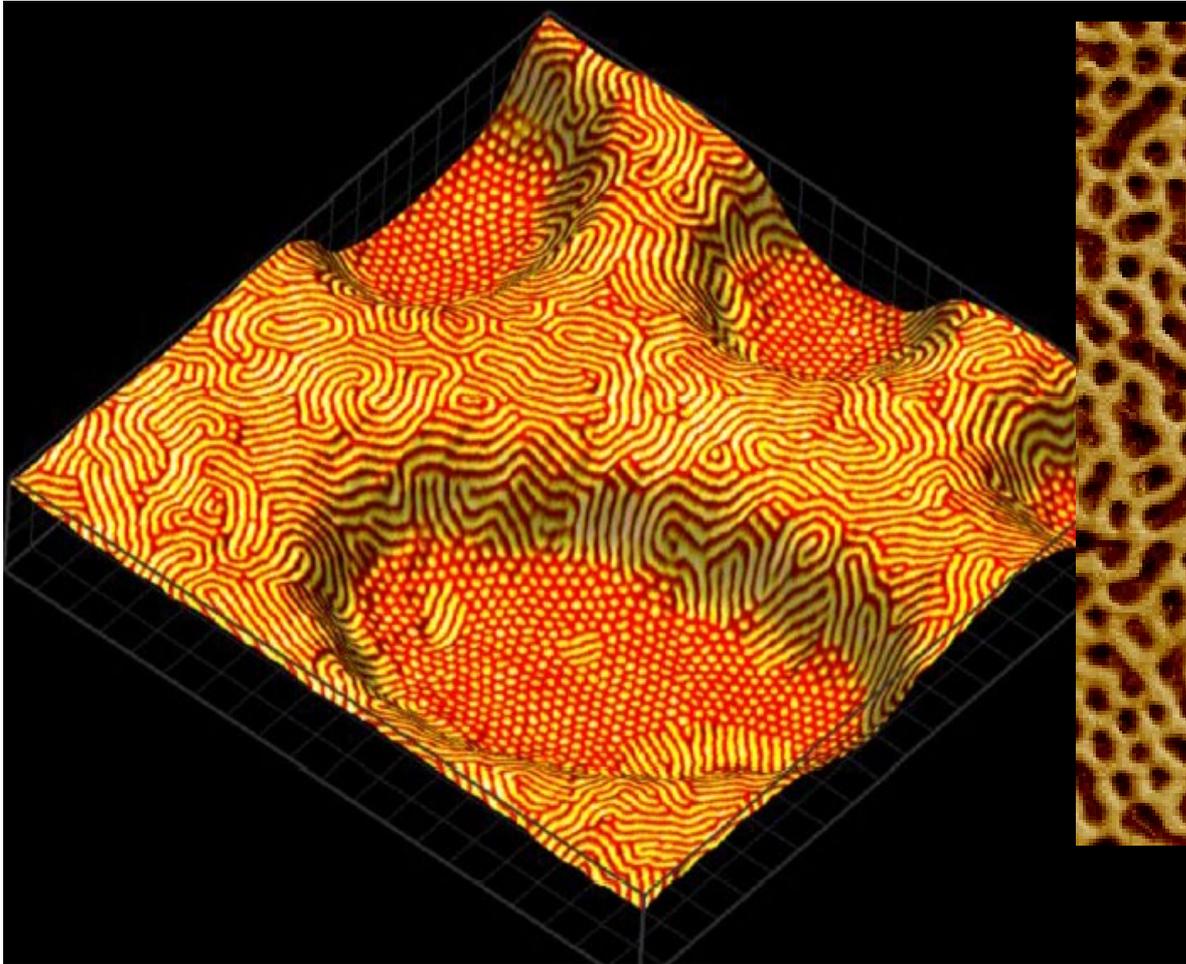
- Originally designed for semiconductor imaging.
- Capable of loading samples up to 350 mm in diameter.
- Large scanning area $\sim 90 \times 90 \mu\text{m}$.
- Automatic measurement for up to 100 pre-selected areas.
- High pixel-density image capture 5120 x 5120 points.

High resolution, easy to use, large samples..

Unfortunately currently broken ..

But Micronova and Chemistry department has other good AFM's

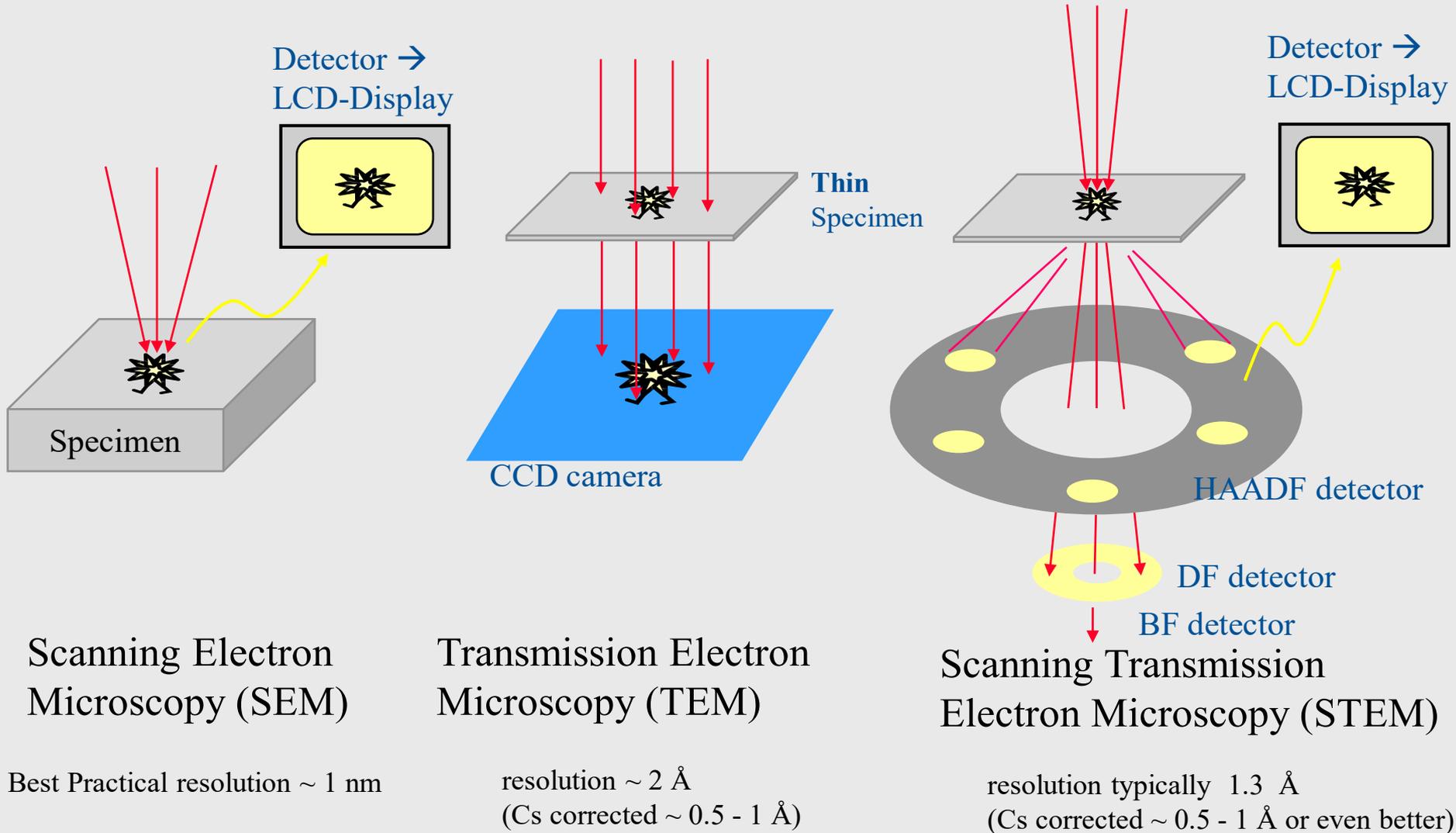
AFM image examples - Polymer films:



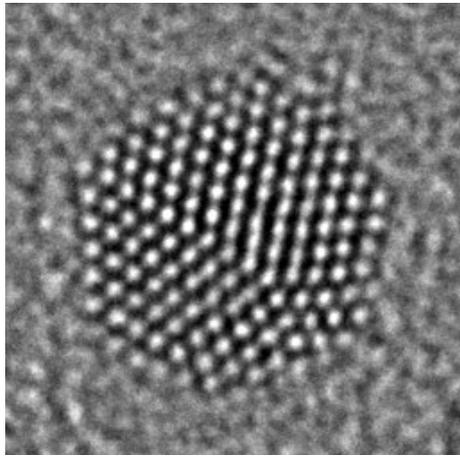
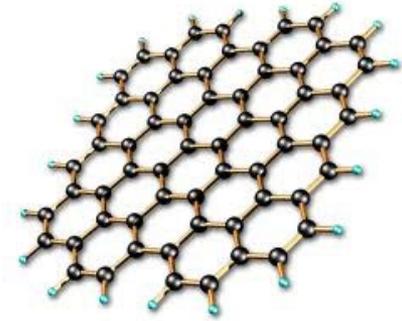
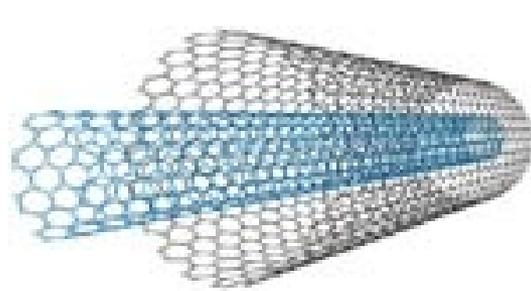
This image dark domains are polyethylene (soft) and gray domains Polystyrene which is glassy polymer.

Topography (height) and composition imaging (soft and hard domains) – in tapping mode imaging one can get at the same time the surface topographical information and contrast due to mechanical properties (example hard of soft domains)

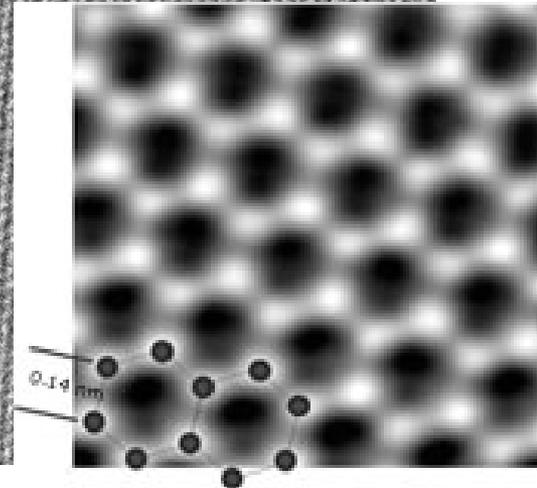
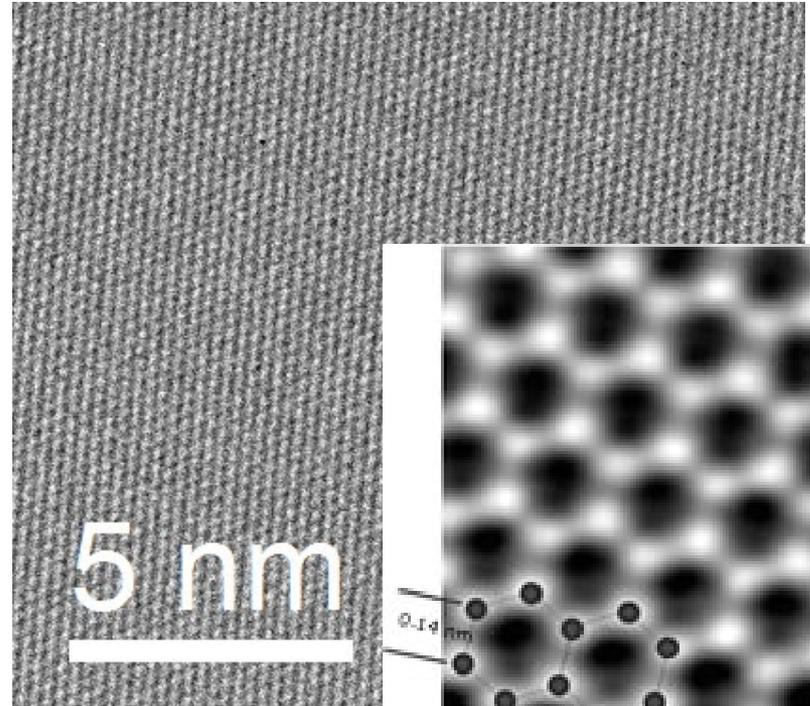
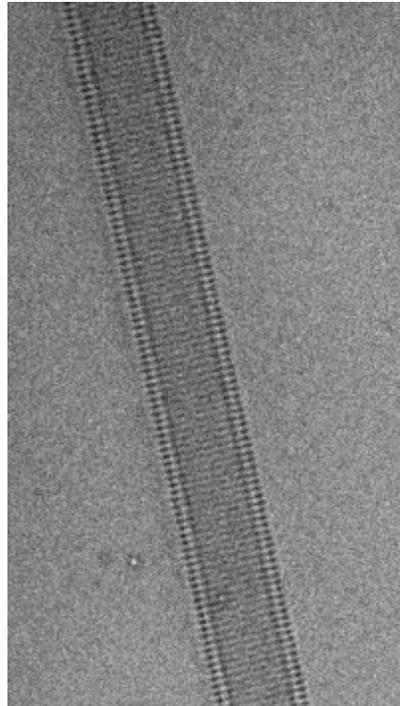
Brief introduction to the electron microscopy



Nowadays it is possible to obtain atomic resolution images even from low atomic number materials such as Carbon nanotubes and single graphene sheets..

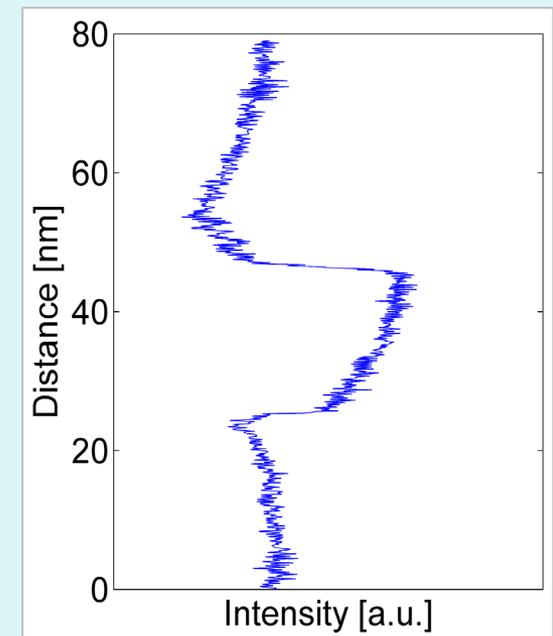
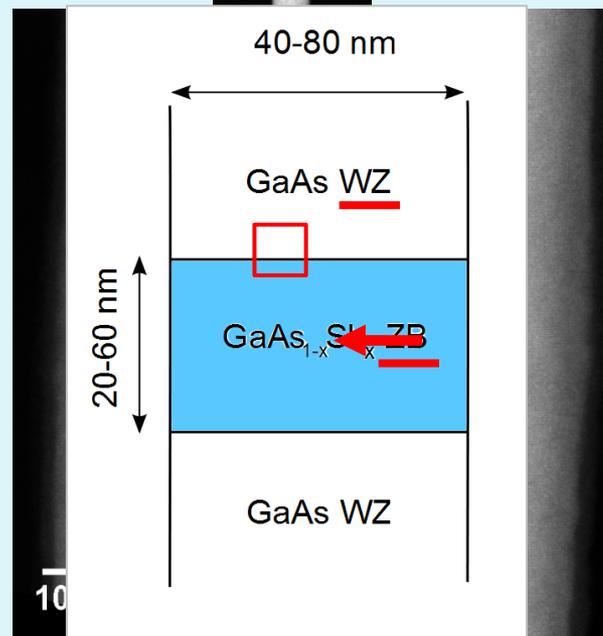


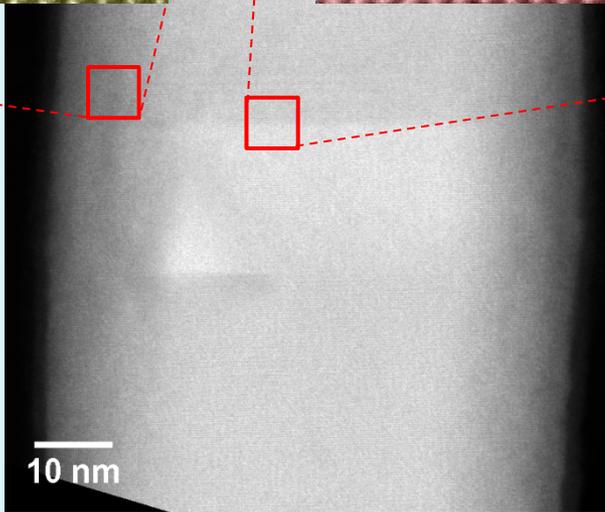
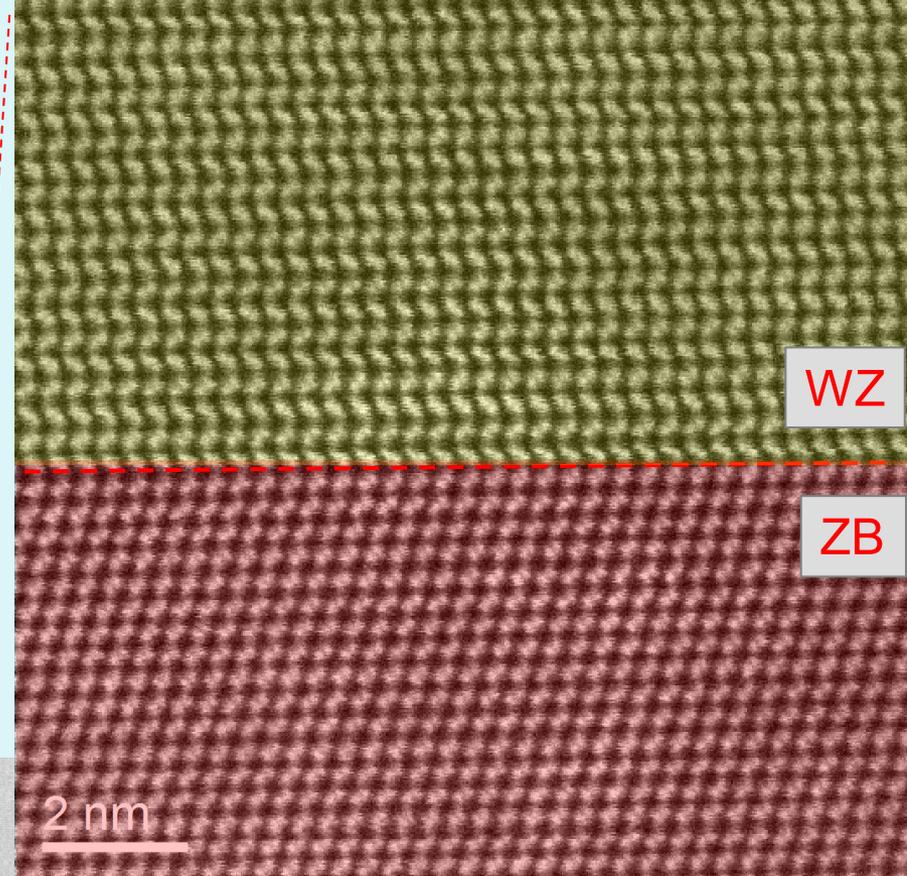
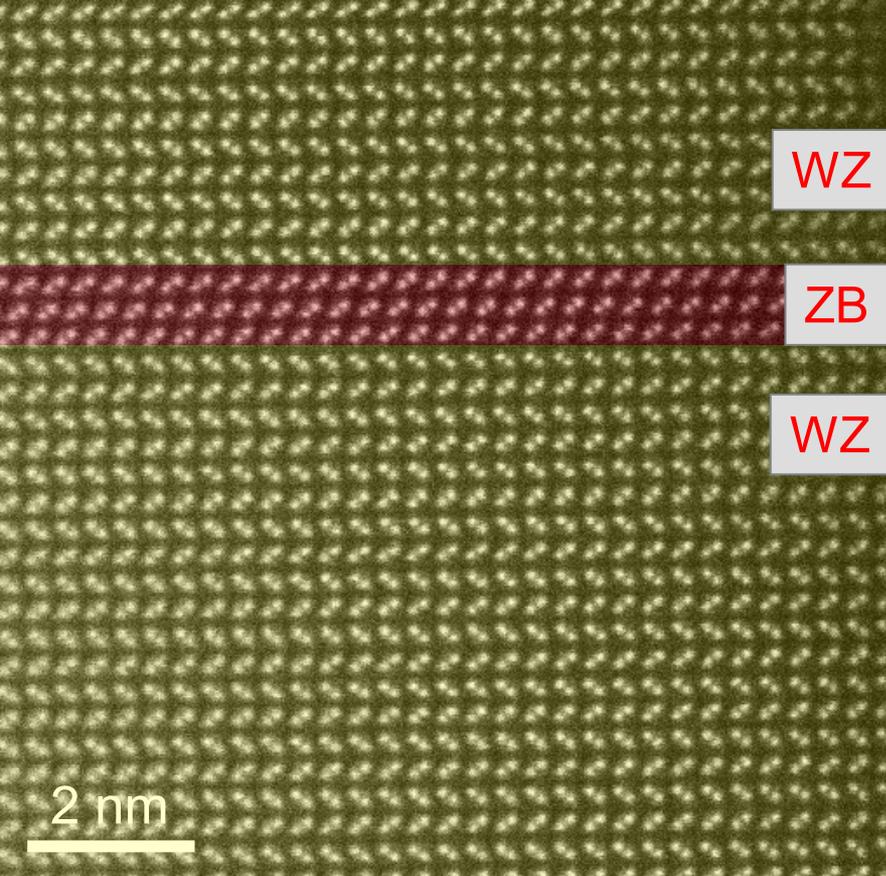
High resolution TEM image from Gold nanoparticles



Another examples: Heterostructured GaAs nanowires

- GaAs nanowires (NWs)
- Molecular beam epitaxial (MBE) growth
- Pure GaAs NWs: Wurtzite (**WZ**) structure (纤锌矿结构, 六方相)
- Partially alloyed with Sb:
GaAs_{1-x}Sb_x insert : Zinc blende (**ZB**) structure (闪锌矿结构, 立方相)



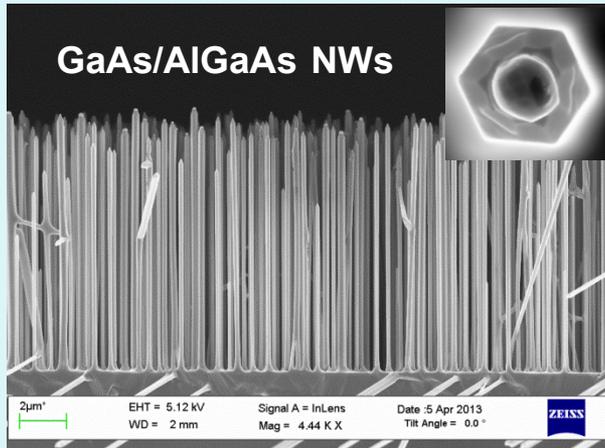


- WZ and ZB coexist;
- Ga and As columns well separated, 1.55 Å;
- Ga and As columns has different intensities.

- Wurtzite structure [11-20] orientation
- Zinc Blende structure [110] orientation

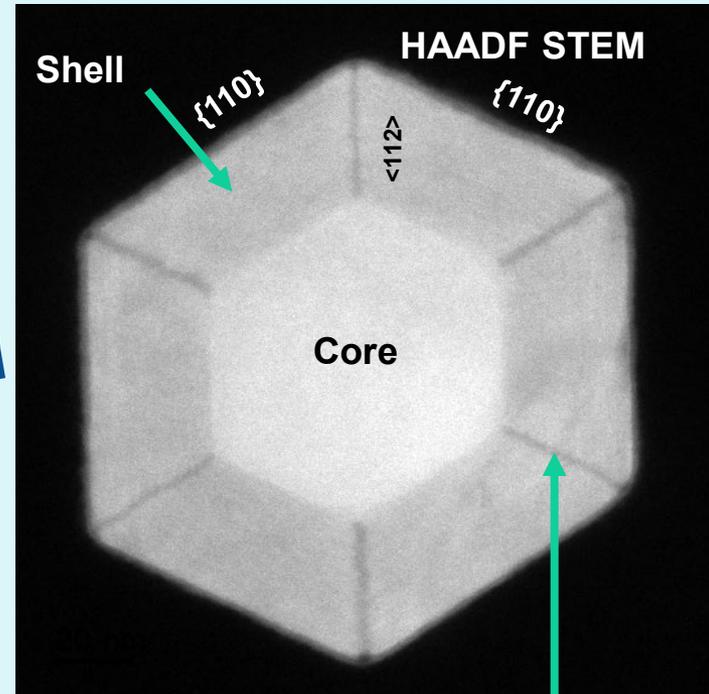
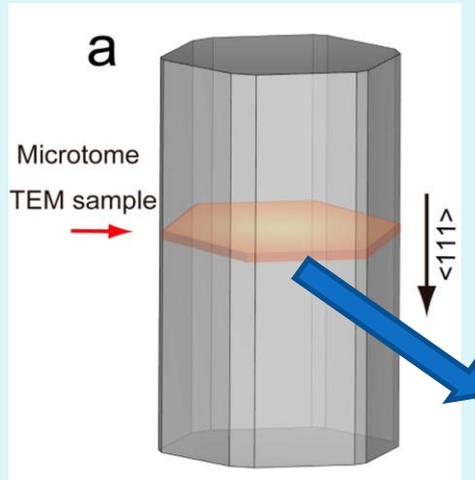
Sample: Hanne Kauko, NTUT

TEM characterization of III-V nanowires (HAADF STEM)

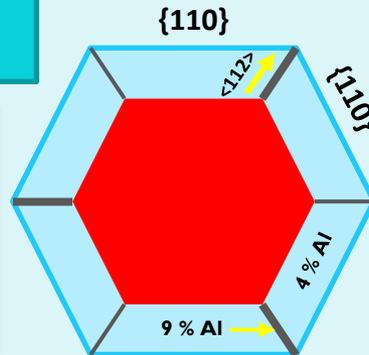


Core-shell GaAs/AlGaAs nanowires grown using MOCVD
60 nm core, 30 nm shell

Al segregation in AlGaAs shell along 6 dark lines
3-fold rotational symmetry (3 thin and 3 thick lines)



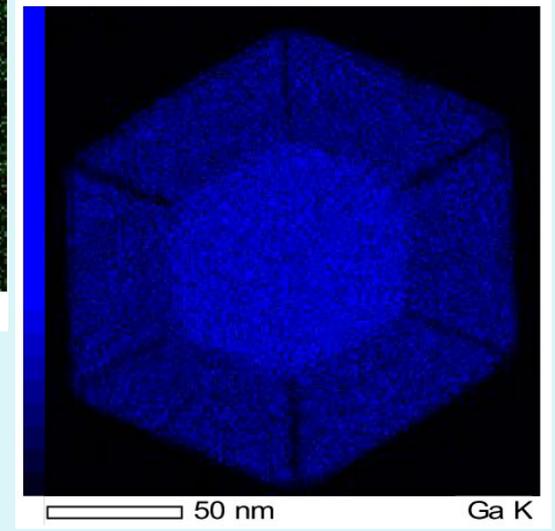
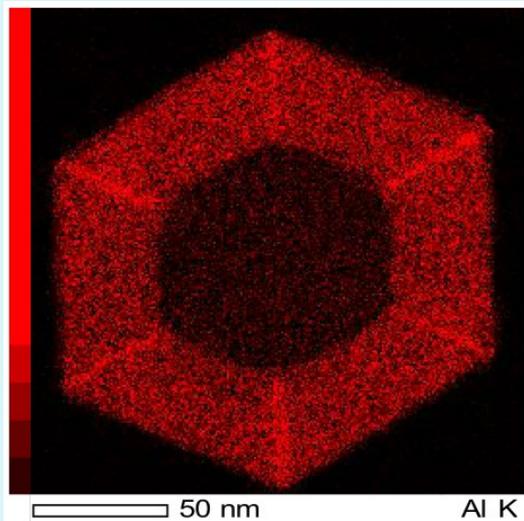
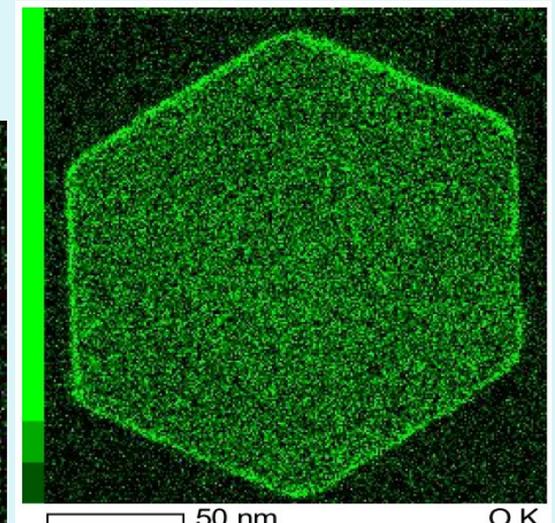
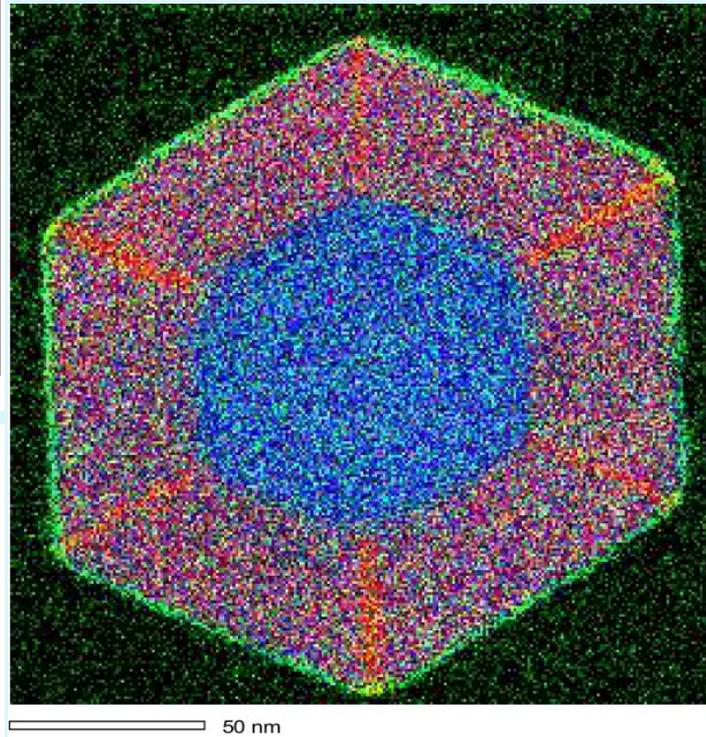
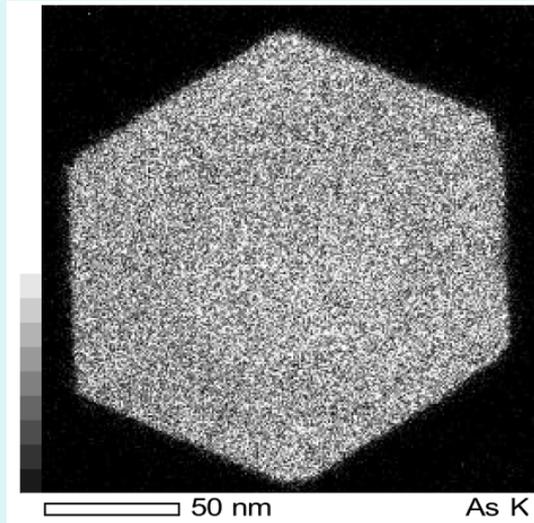
Dark lines (Al segregation)
Cross section view



Dhaka et al., Nano Letters, 2013, 13 (8), pp 3581–3588

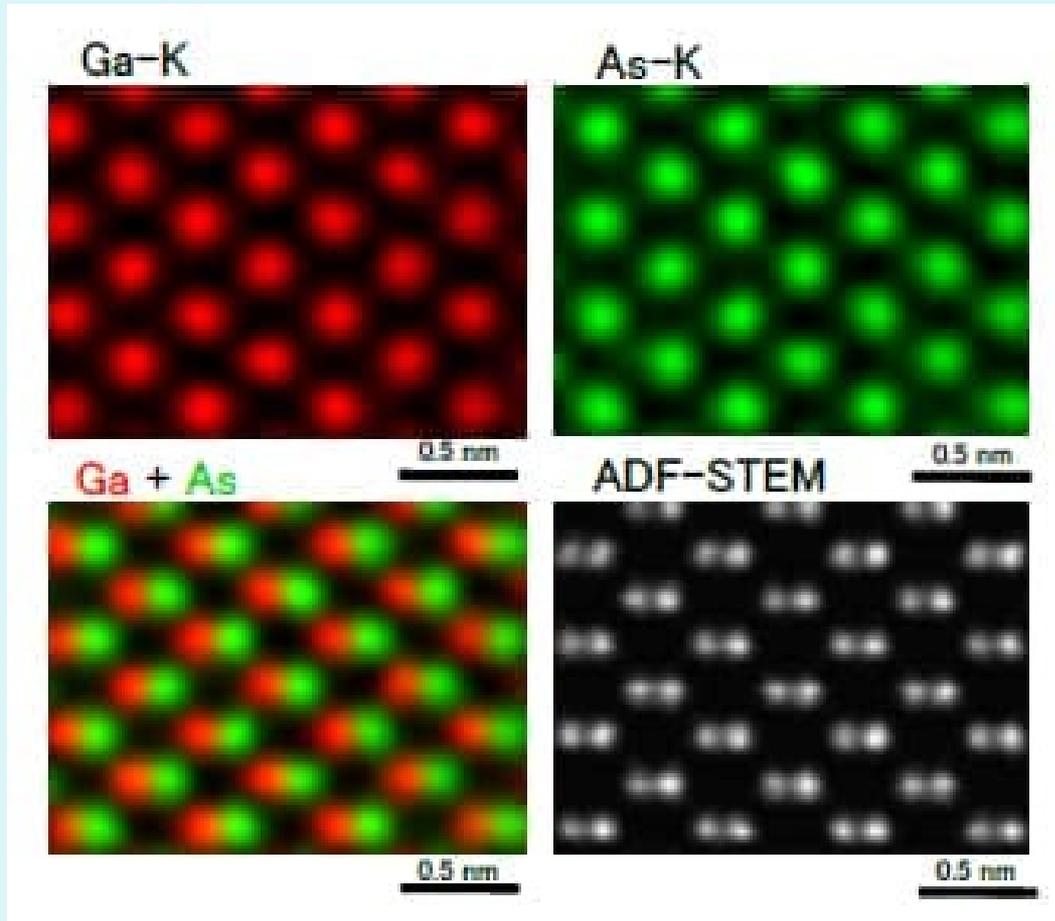
Elemental Mapping of cross-sectional GaAs nanowires

by analysing the X-ray signals generated in the sample – atomic composition can be analysed (EDX-spectroscopy)



Sample: Veer Dhaka, Aalto U.

Atomic resolution elemental analysis is also possible with modern high resolution microscopes..



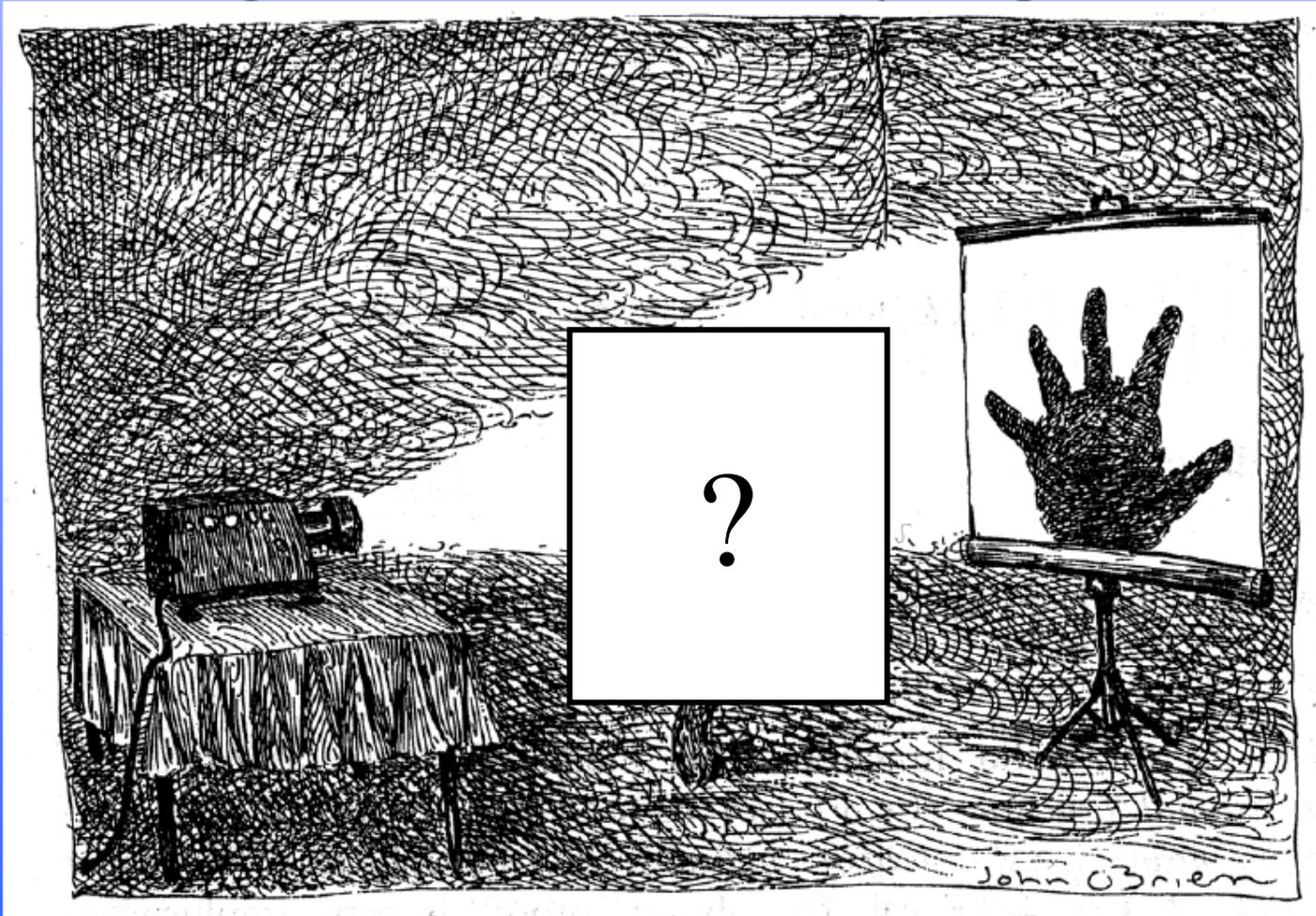
Atomic-level-resolution EDX elemental map of a gallium arsenide monocrystal $\langle 011 \rangle$

3D tomography – Why important?

(Jani Seitsonen will give lecture on this topic later in the spring)

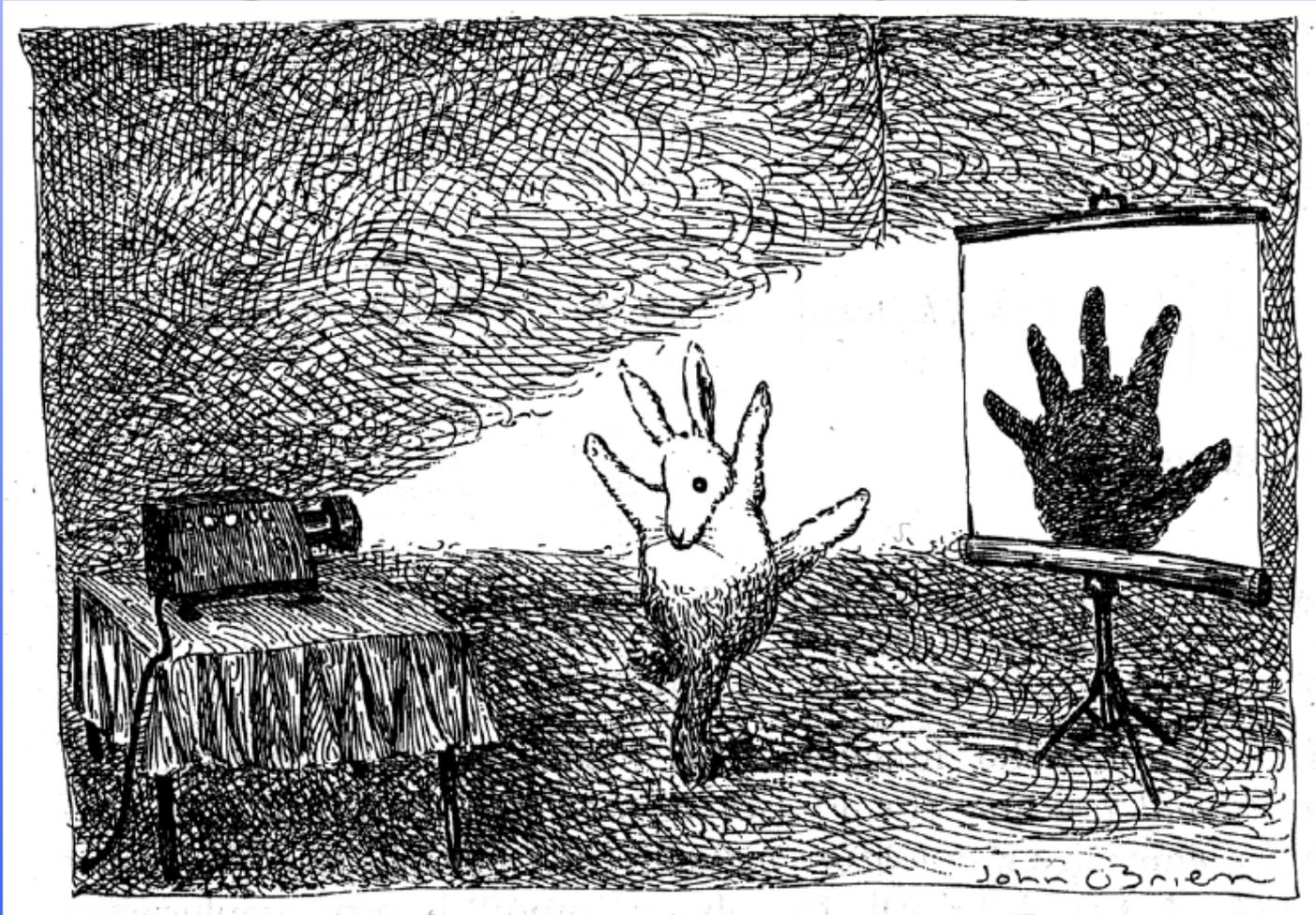
TEM image is projection from 3D \rightarrow 2D

- Micrograph represents a projection image of the specimen. So features at different depths in the structure are all superimposed. Hence cannot generate a 3D structure by simple visual inspection.



TEM image is projection from 3D \rightarrow 2D

- Micrograph represents a projection image of the specimen. So features at different depths in the structure are all superimposed. Hence cannot generate a 3D structure by simple visual inspection.





Another example of projection from 3D \rightarrow 2D



Another example of projection from 3D → 2D

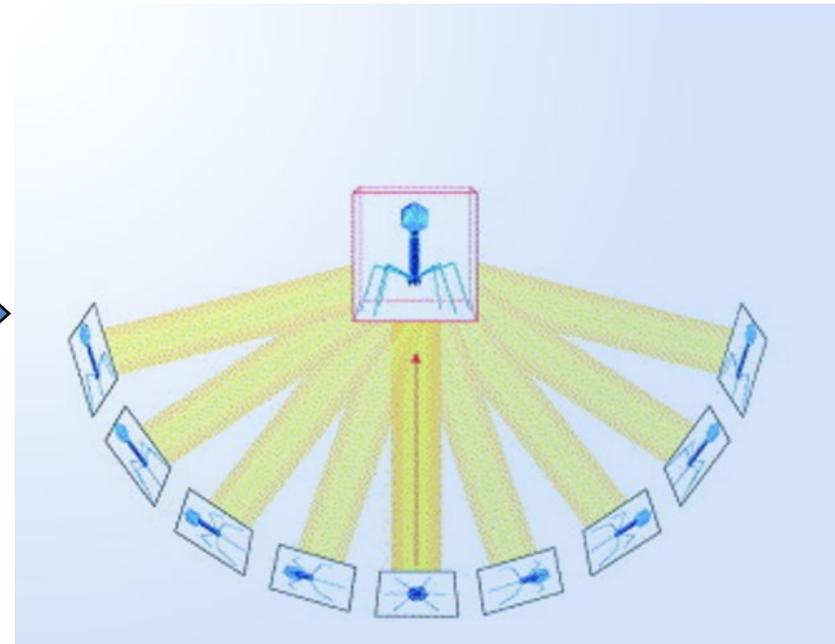
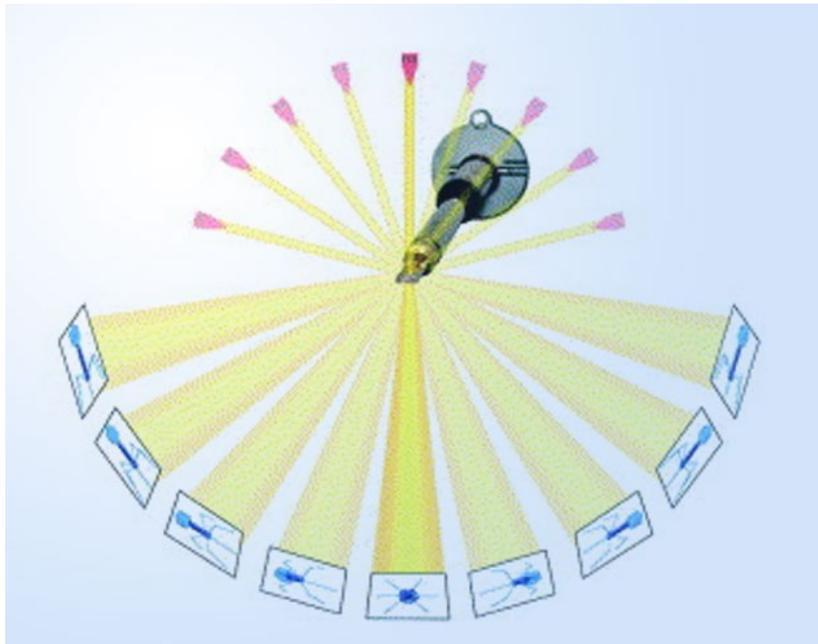


When 2D-projections are not enough: TOMOGRAPHY (or single particle reconstruction)

Principle of electron tomography:

DATA COLLECTION

RECONSTRUCTION



3D object => 2D-projections

2D-projections => 3D-reconstruction

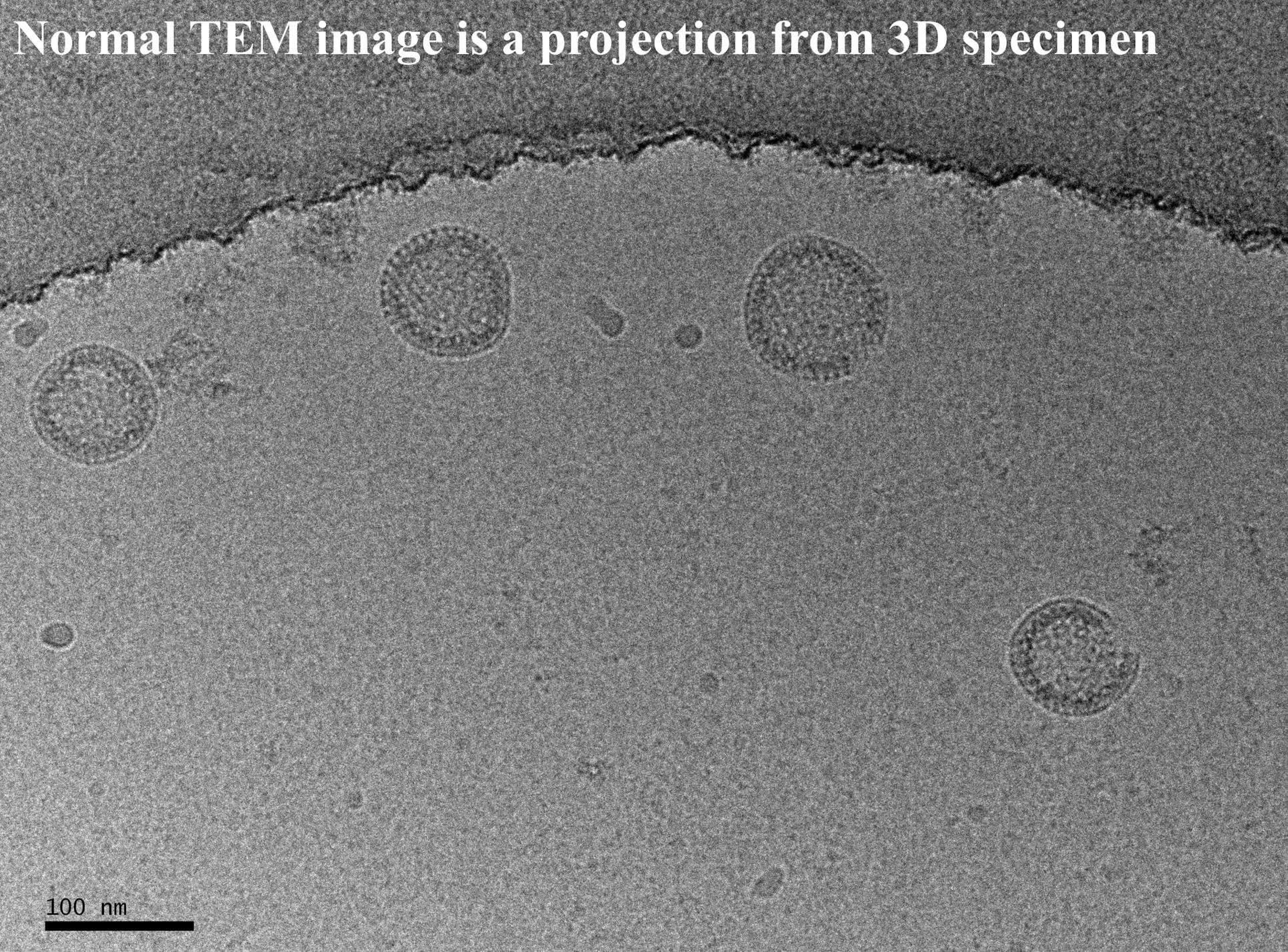
Cryo-Tomography

Case study: Cryo-EM structure of **M-PMV VLPs**

Sample: *in vitro* assembled **V**irus-**L**ike **P**articles of **M**ason-**P**fizer
Monkey **V**irus

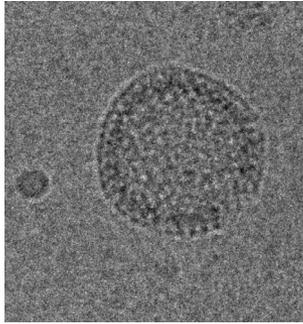
(Pasi Laurinmäki, Institute of Biotechnology
University of Helsinki)

Normal TEM image is a projection from 3D specimen



100 nm

3D cryo-EM: aligned tomographic tilt series

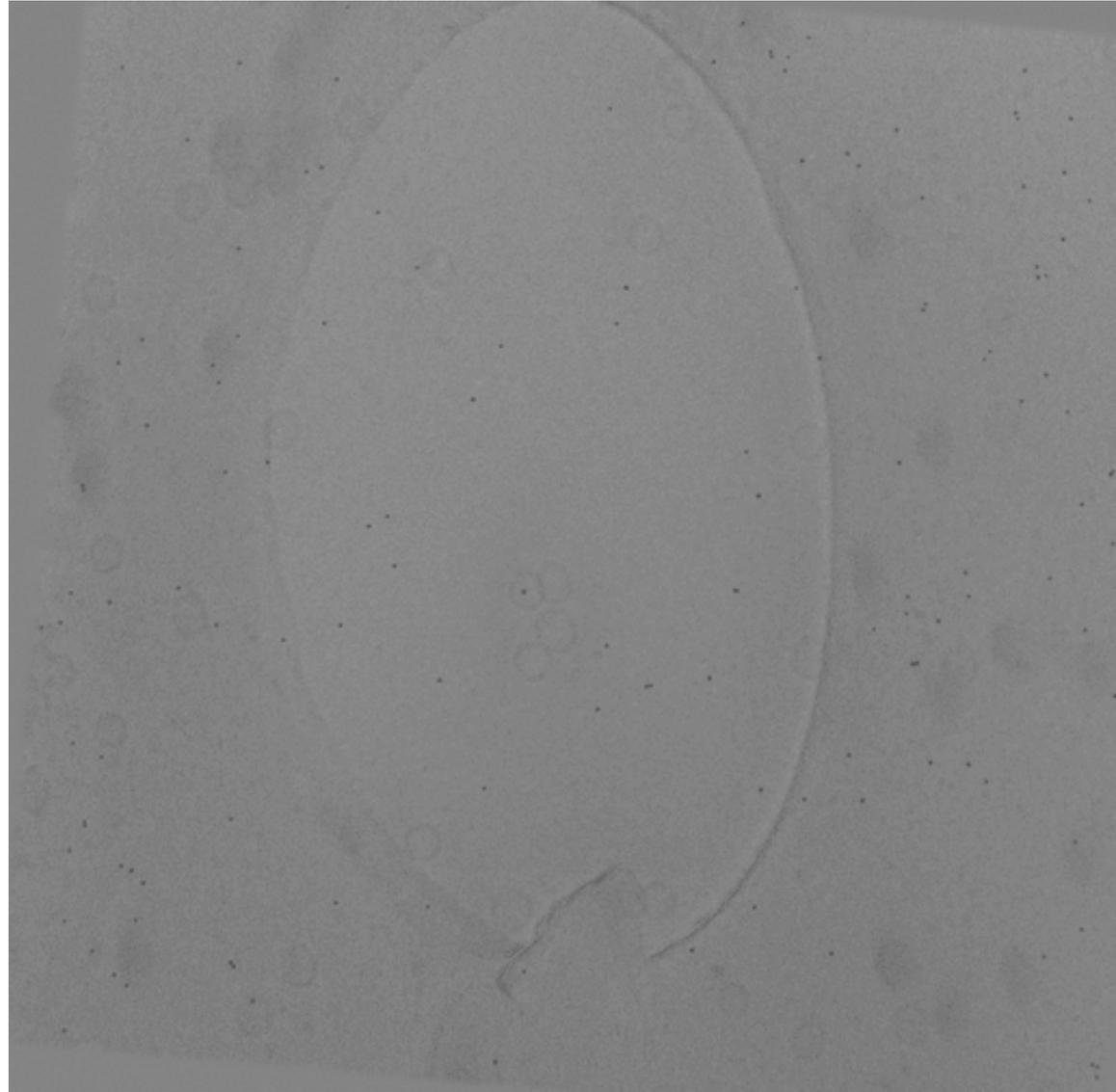


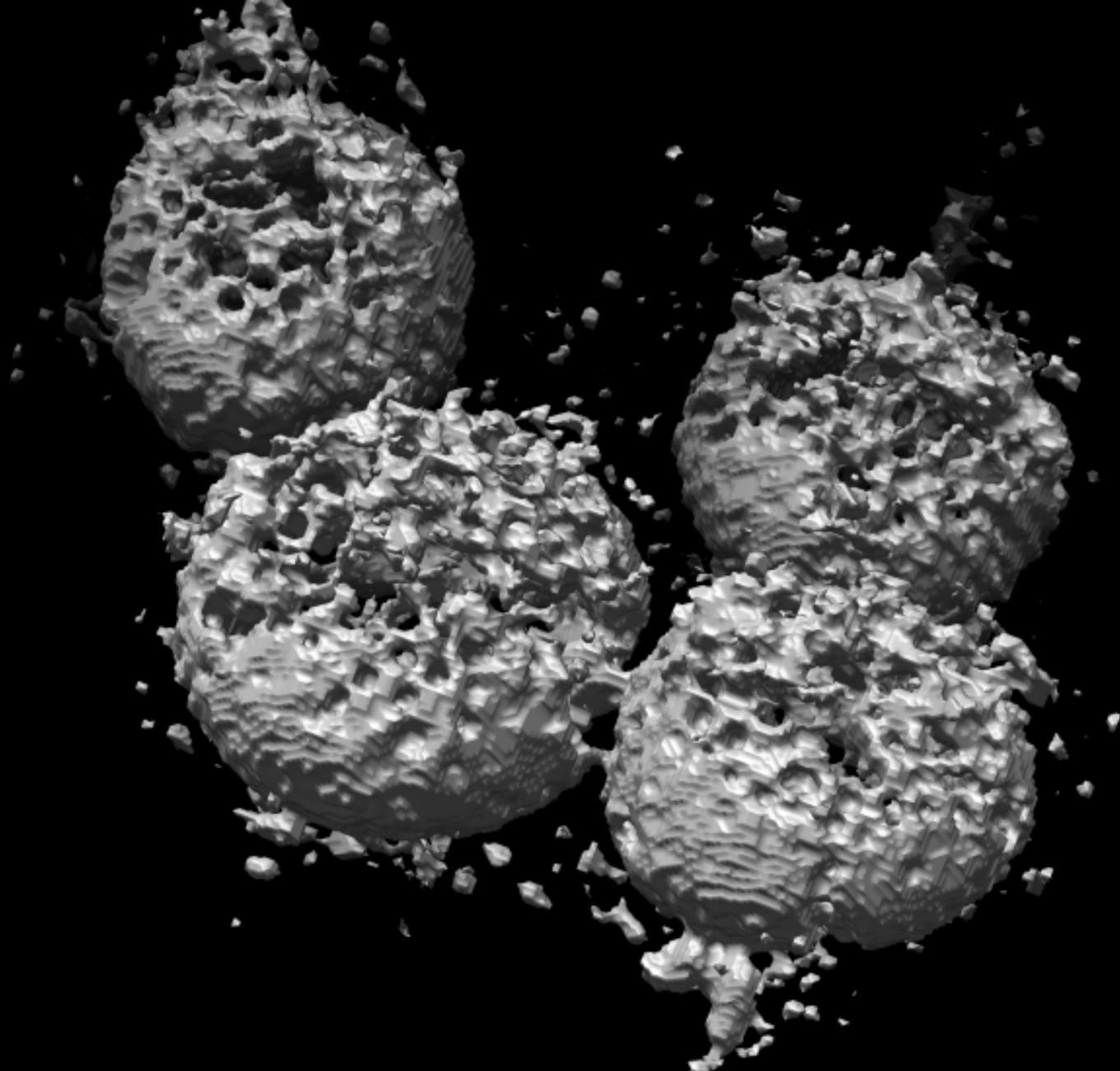
Low-dose series of *in vitro* assembled proCANC M-PMV particles

Diameter of the large round hole is about 2 μ m

Dense dots are 10nm gold particles used as markers to align the images

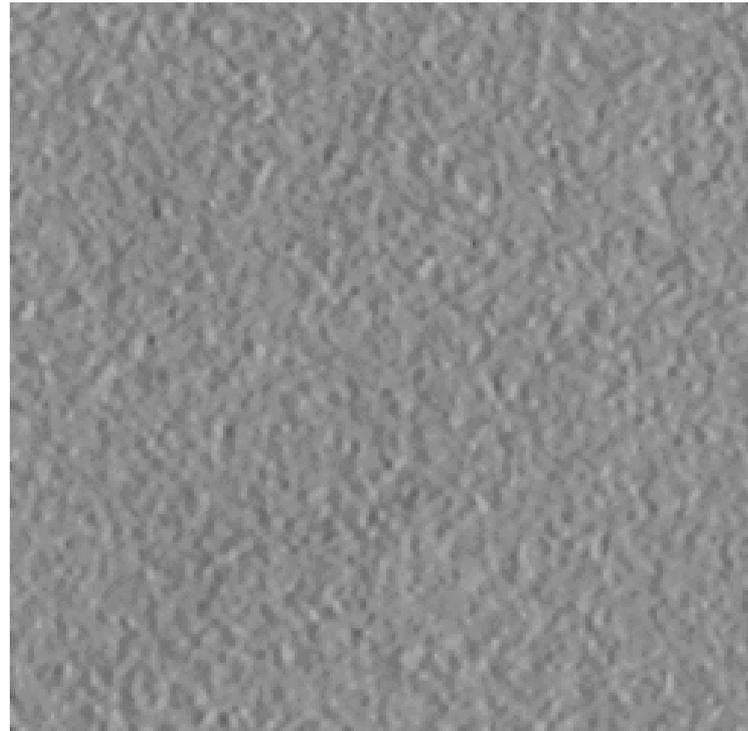
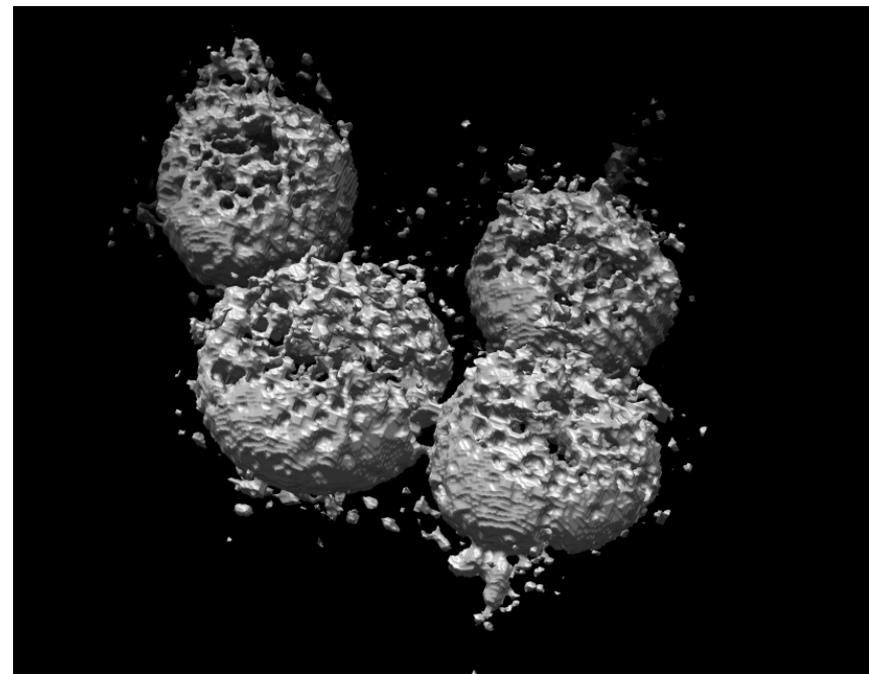
Then we just take images from -70 to +70 degree tilt and do 3D reconstruction



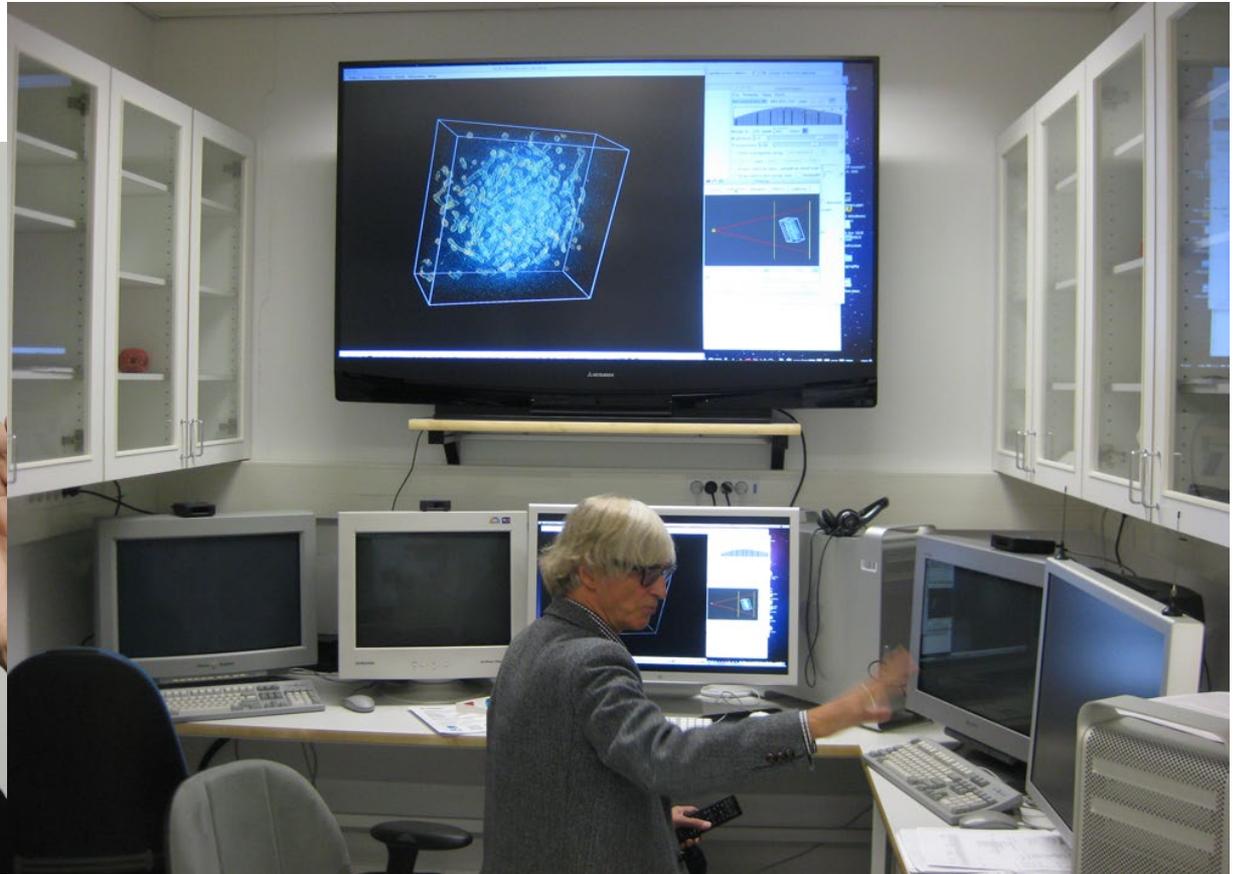


Surface representation of the reconstructed density

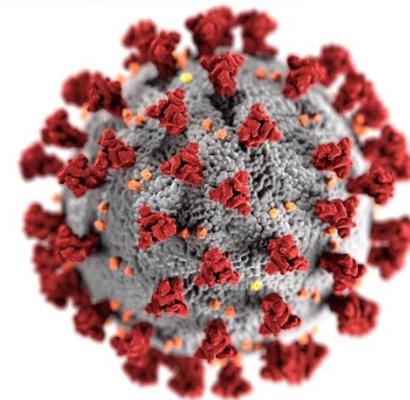
Serial sections through the reconstructed density



3D structure visualization by using computers and 3D glasses..



Using similar 3D imaging methods also the structure of the **SARS-CoV-2** virus was resolved (single particle reconstruction)

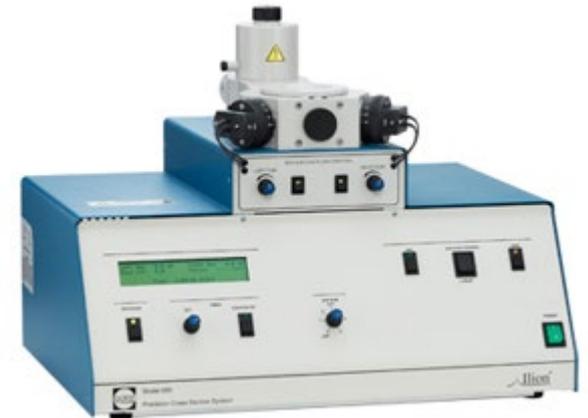


Sample preparation for TEM: THIN SPECIMENS

A major limitation of the TEM is we need thin specimens.

Methods to prepare thin specimens exist for almost all materials, and we talk about them specific lecture. But as a general rule, the thinning processes that we use do affect the specimens, changing both their structure and chemistry. So you need to be aware of the drawbacks of specimen preparation and learn to recognize the artifacts introduced by standard preparation methods.

Ultramicrotoming, ion milling, Focused ion beam, cryo sample preparation etc..



Planar Surface Preparation for SEM Cross Section Viewing

New Dual beam focused ion beam system in Nanomicroscopycenter (installation finished by June 2019): Main applications **TEM sample preparation, cross-section imaging and 3D imaging ... (also nano fabrication and IC device failure analyses)**

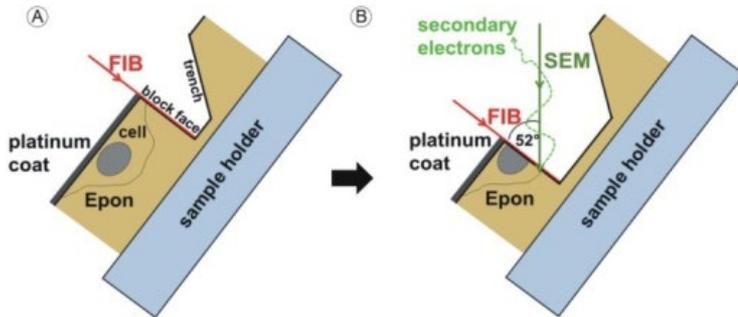
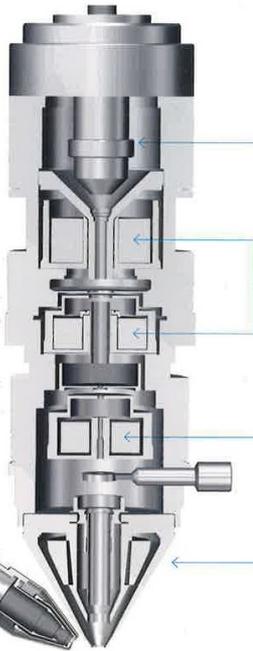
FIB: 3 functions:

- 1. Milling** (Gallium ions)
- 2. Deposition** (metal coatings like Pt or Carbon)
- 3. Imaging** SEM

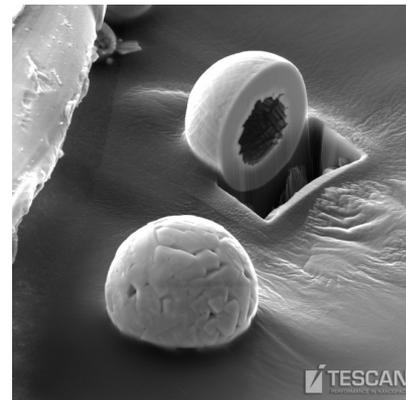
FIB-column



SEM-column

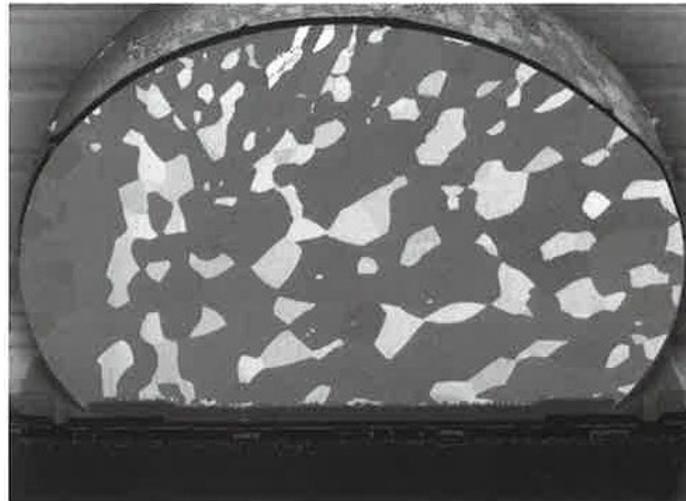
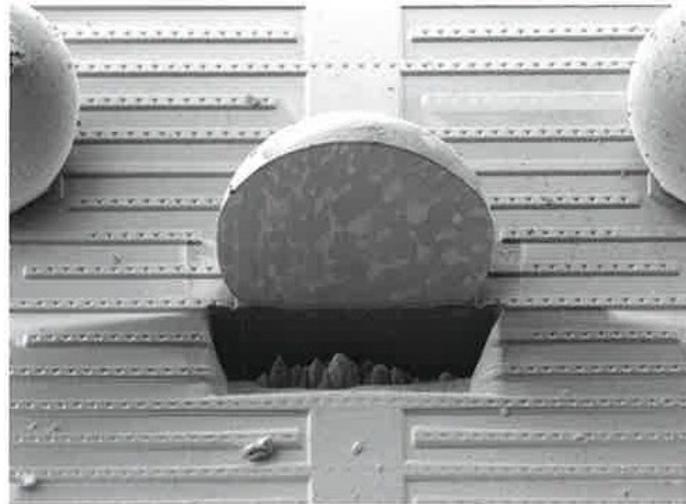


3D imaging



Here is the example of cross-section imaging: FIB column is used to cut the cross-section and SEM column for imaging

Example: FIB cross-section imaging from soldering tin particles



TEM sample preparation using Focused ion beam..

FIB is very useful for hard materials thin cross-section sample preparation – after final polishing << 100 nm meter thick sample can be done

